

# Compal Confidential

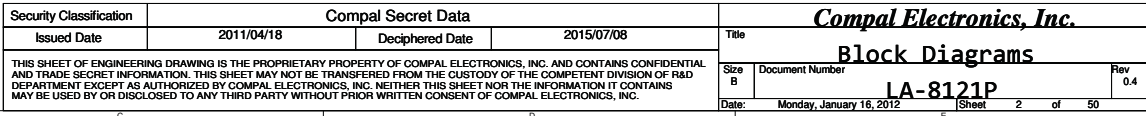
## QALEA/QALEB Schematics Document

AMD APU Trinity FS1r2 + FCH Hudson-M3 + GPU Seymour XTX/Thames XT

2012-01-16

REV: 0.4

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Voltage Rails

Power Plane	Description	S0	S3	S5
VIN	Adapter power supply (19V)	N/A	N/A	N/A
B+	AC or battery power rail for power circuit.	N/A	N/A	N/A
+APU_CORE	Core voltage for APU	ON	OFF	OFF
+APU_CORE_NB	Voltage for On-die VGA of APU	ON	OFF	OFF
+1.5V	1.5V power rail for APU VDDIO and DDR	ON	ON	OFF
+0.75VS	0.75V switched power rail for DDR terminator	ON	OFF	OFF
+1.2VS	1.2V (VDDR, VDDP) switched power rail for APU	ON	OFF	OFF
+2.5VS	2.5V for APU VDDA	ON	OFF	OFF
+1.1VALW	1.1V switched power rail for FCH	ON	ON	ON*
+1.1VS	1.1V switched power rail for FCH	ON	OFF	OFF
+1.5VS	1.5V switched power rail	ON	OFF	OFF
+VGA_CORE	0.95-1.2V switched power rail	ON	OFF	OFF
+1.5VGS	1.5V switched power rail	ON	OFF	OFF
+1.8VGS	1.8V switched power rail	ON	OFF	OFF
+1.0VGS	1.0V switched power rail for VGA	ON	OFF	OFF
+3VALW	3.3V always on power rail	ON	ON	ON*
+3VS_WLAN	3.3V power rail for WLAN	ON	OFF	OFF
+3VS	3.3V switched power rail	ON	OFF	OFF
+5VALW	5V always on power rail	ON	ON	ON*
+5VS	5V switched power rail	ON	OFF	OFF
+VSB	VSB always on power rail	ON	ON	ON*
+RTCVCC	RTC power	ON	ON	ON

Note : ON\* means that this power plane is ON only with AC power available, otherwise it is OFF.

FCH Hudson-M2/3  
SATA Port List

SATA0	HDD
SATA1	ODD
SATA2	NC
SATA3	NC
SATA4	NC
SATA5	NC

Comal  
PCIE Port List

APU	PCIE0	LAN
	PCIE1	WLAN
	PCIE2	NC
	PCIE3	Card Reader
FCH	PCIE0	NC
	PCIE1	NC
	PCIE2	NC
	PCIE3	NC

FCH Hudson-M2/3  
USB Port List

USB1.1	
Port0	NC
Port1	NC
USB2.0	
Port0	USB2.0 Port
Port1	NC
Port2	NC
Port3	NC
Port4	NC
Port5	WLAN
Port6	CMOS
Port7	FP
Port8	BT
Port9	NC
Port10	USB 3.0
Port11	USB 3.0
Port12	USB 3.0
Port13	NC

EC SM Bus1 address                      EC SM Bus2 address

Device	Address	HEX	Device	Address	HEX
Smart Battery	0001-011xb	15H	F75303 (DDR,VRAM,CPUCORE)	1001-101xb	9AH
			SB-TSI	1001-100xb	98H
			Seymour XTX	1000-0010b	82H
			LVDS translator		

BOM Structure

UMA@ : UMA only  
DIS@ : DIS muxluss  
PX40@ : PX4.0 Support  
PX50@ : PX5.0 Support  
CMOS@ : USB camera

CONN@ : ME components  
X76@, H2G@, S2G@ : VRAM

Tha@: Thames VGA  
Sey@: Seymour VGA

BOM option and stencil

SDV:  
CMOS@/DIS@/PX40@/SEY@ + X76@

PJ201,PJ401,PJ502,PJ503,PJ504,PJ601,PJ603,PJ604,  
PJ701,PJ702,PJ703,PJ704,J1,J2301,J2401,J2402,J2403  
PJ402,PJ403,PJ501,PJ602,PJ801,PJ802,PJ803,PJ804,PJ805

FCH SMB0 (FCH\_SMB0)

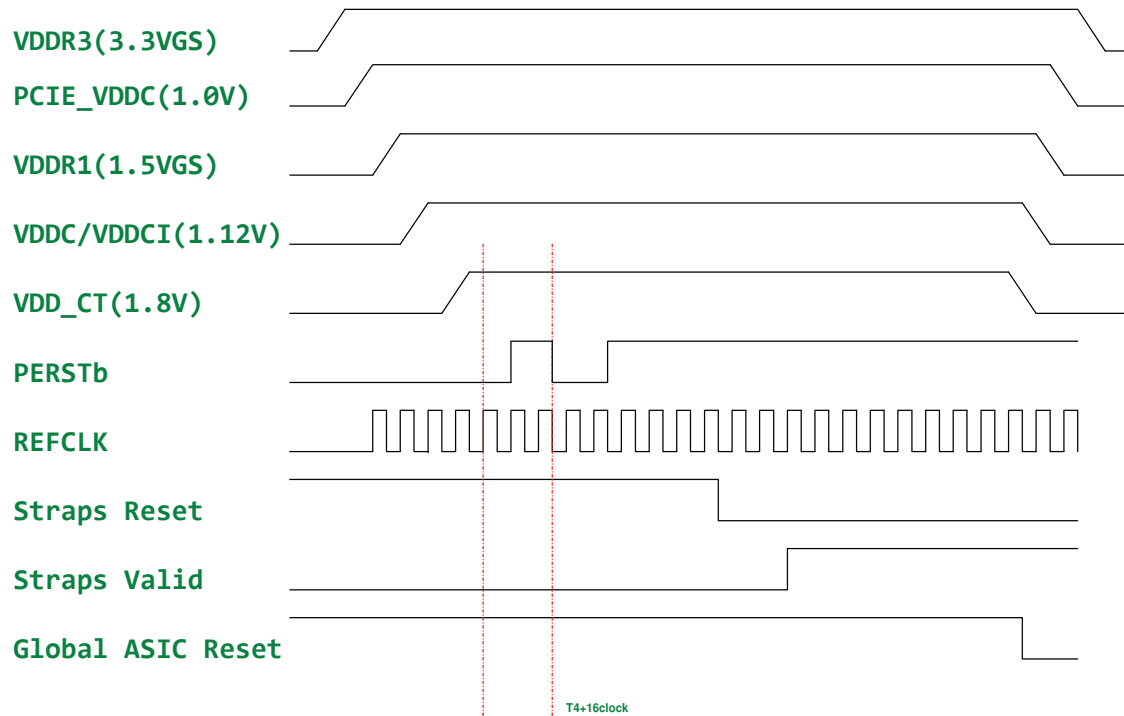
Device	Address	HEX
DDR DIMM1 (FCH_SMB0)	1001-000xb	90
DDR DIMM2 (FCH_SMB0)	1001-001xb	92
WLAN (FCH_SMB0)		
Security ROM		

Stencil Memo

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## Power-Up/Down Sequence

- All the ASIC supplies, except for VDDR3, must fully reach their respective nominal voltages within 20 ms of the start of the ramp-up sequence, though a shorter ramp-up duration is preferred. There is no timing requirement on the ramp up of VDDR3 relative to other power rails.
- The external pull-up resistors on the DDC/AUX signals (if applicable) should ramp up before or after both VDDC and VDD\_CT have ramped up.
- VDDC and VDD\_CT should not ramp up simultaneously. For example, VDDC should reach 90% before VDD\_CT starts to ramp up (or vice versa).
- For power down, reversing the ramp-up sequence is recommended.



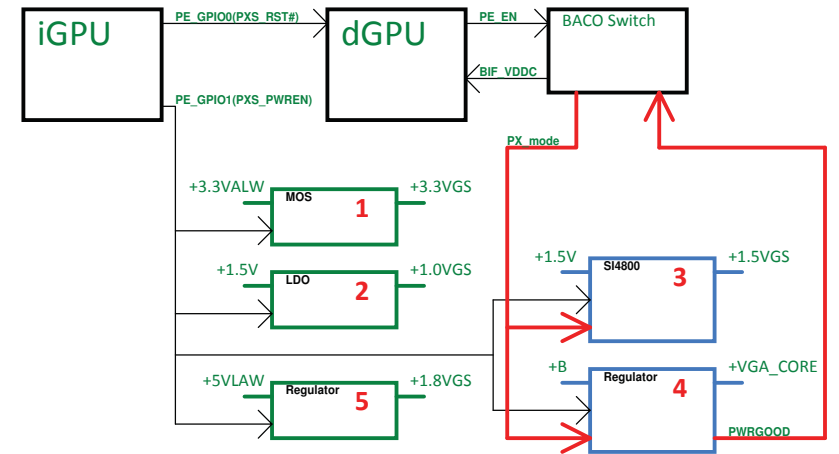
## Without BACO option :

PE\_GPIO0 : Low -> Reset dGPU ; High -> Normal operation  
 PE\_GPIO1 : Low -> dGPU Power OFF ; High -> dGPU Power ON

## BACO option :

PE\_GPIO0 : High -> Normal operation (dGPU is not reset on BACO mode)  
 PE\_GPIO1 : Low -> dGPU Power OFF ; High -> dGPU Power ON (always High)

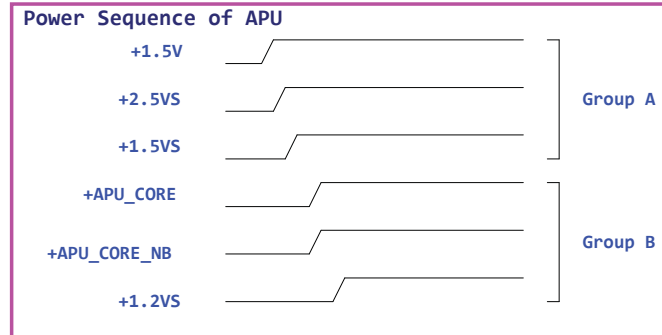
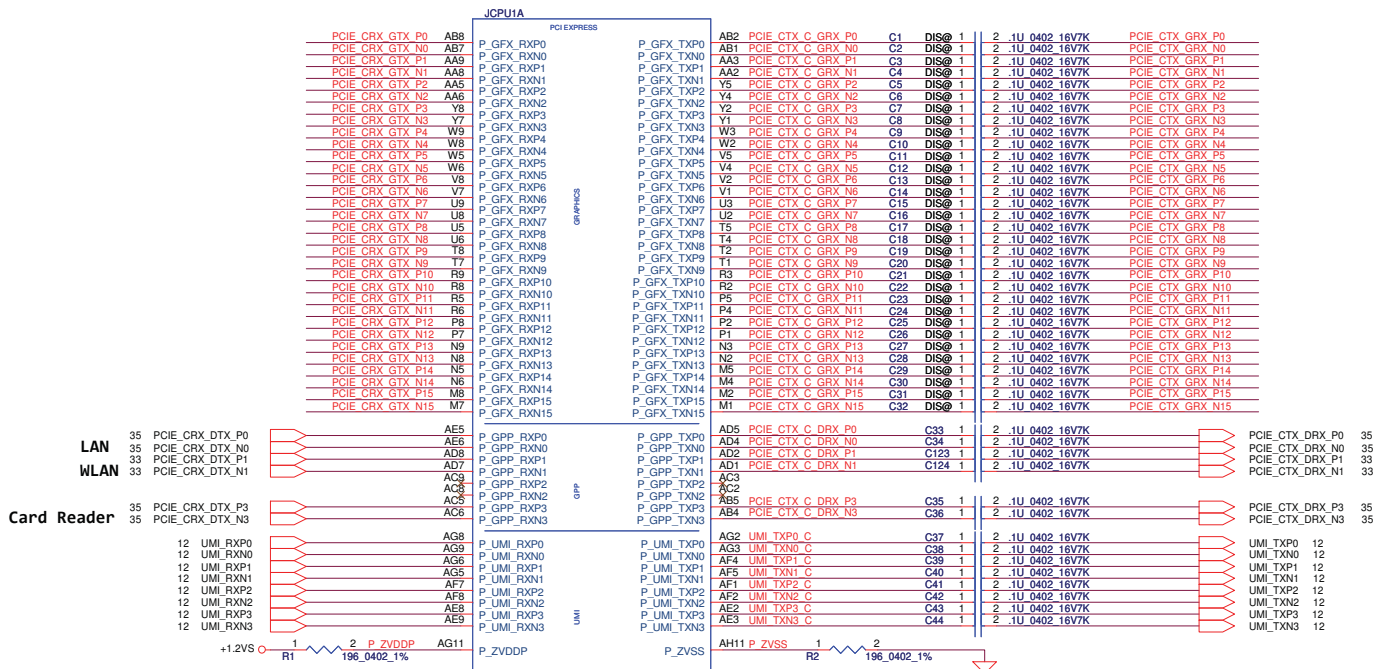
dGPU Power Pins	Voltage	PX 3.0	BACO Mode	Max current
PCIE_PVDD, PCIE_VDDR, TSVDD, VDDR4, VDD_CT, DPE_PVDD, DP[F:E]_VDD18, DP[D:A]_PVDD, DP[D:A]_VDD18, AVDD, VDD1DI, A2VDDQ, VDD2DI, DPLL_PVDD, MPV18, and SPV18	1.8V	OFF	ON	1679mA
DP[F:E]_VDD10, DP[D:A]_VDD10, DPLL_VDDC, and SPV10	1.0V	OFF	ON	775mA
PCIE_VDDC	1.0V	OFF	ON	1.1A
VDDR3	3.3V	OFF	ON	60mA
BIF_VDDC (current consumption = 55mA@1.0V, in BACO mode)	Same as VDDC	OFF	ON Same as PCIE_VDDC	70mA
VDDR1	1.5V	OFF	OFF	1.2A
VDDC/VDDCI	TBD	OFF	OFF	28



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17 PCIE\_CRX\_GTX\_P[0..15] 17  
17 PCIE\_CRX\_GTX\_N[0..15] 17

PCIE\_CTX\_GRX\_P[0..15] 17  
PCIE\_CTX\_GRX\_N[0..15] 17



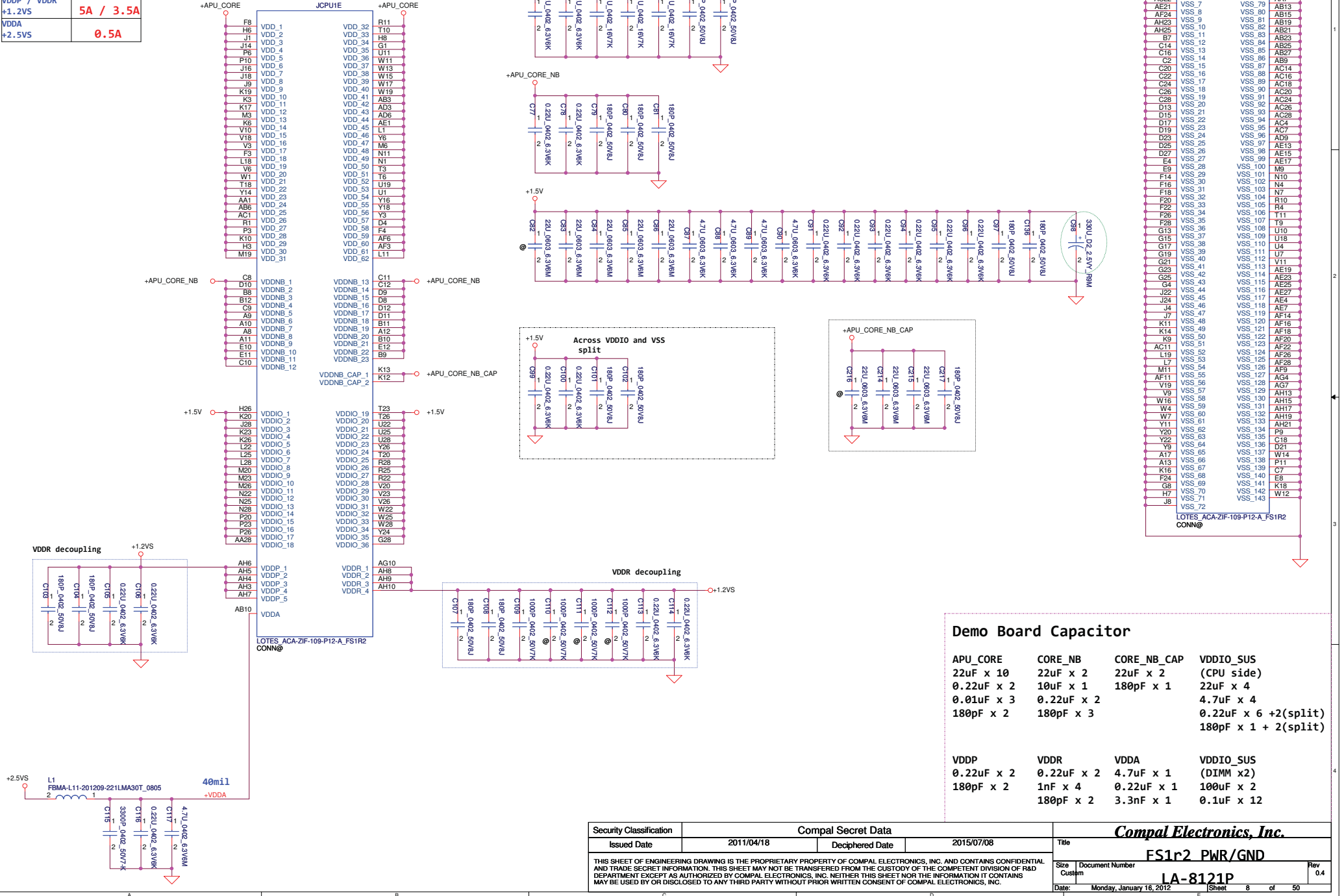
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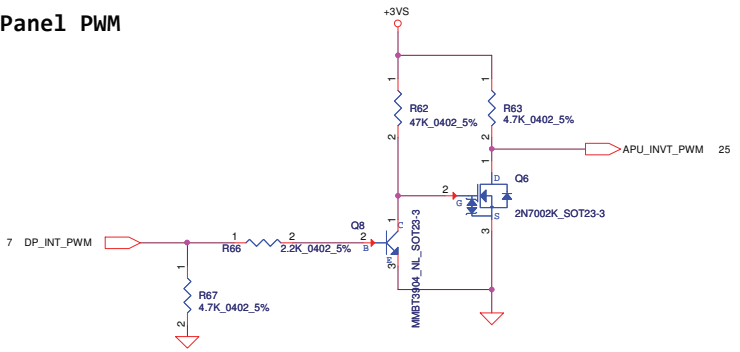
Power Name	Consumption
VDD +APU_CORE	60A
VDDNB +APU_CORE_NB	44A
VDDIO +1.5V	3.2A
VDDP / VDDR +1.2VS	5A / 3.5A
VDDA +2.5VS	0.5A





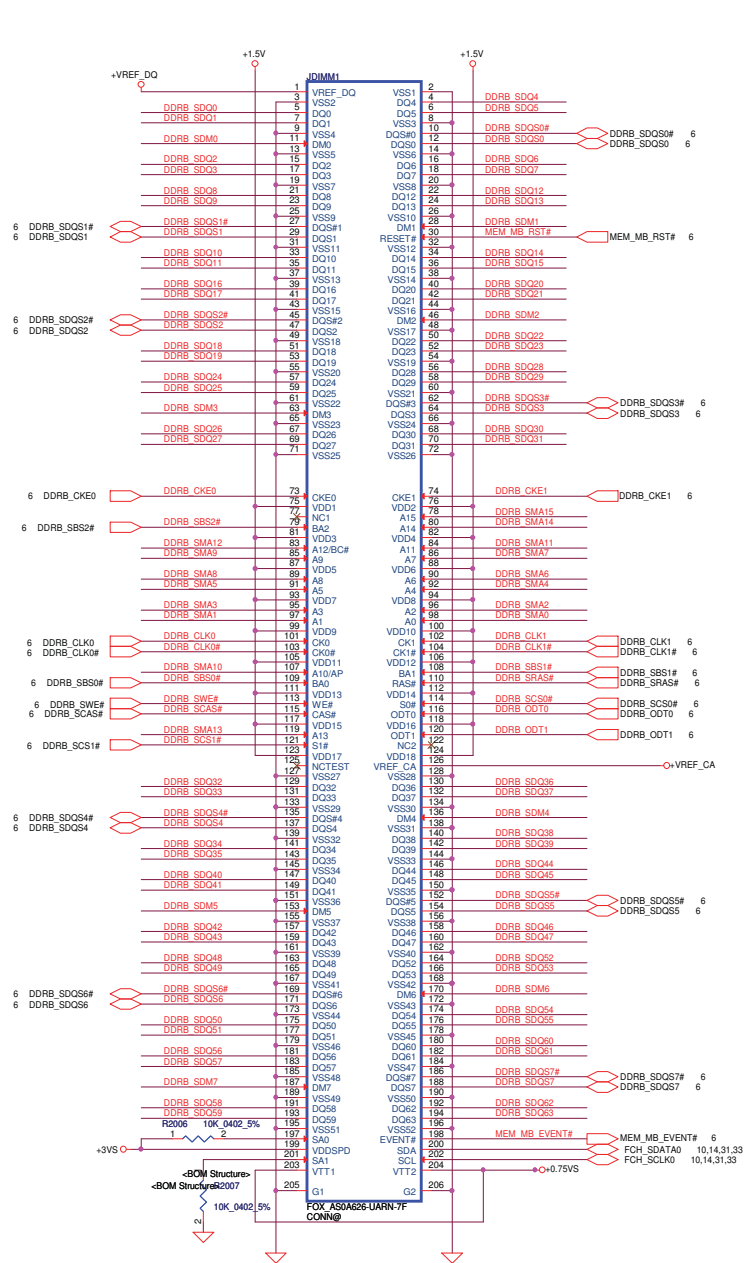
HPD  
SIT, NO.4

Panel PWM



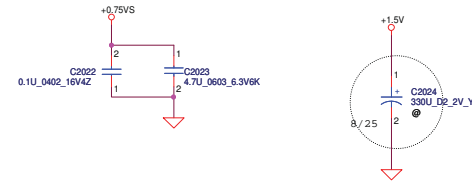
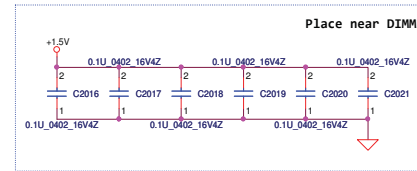
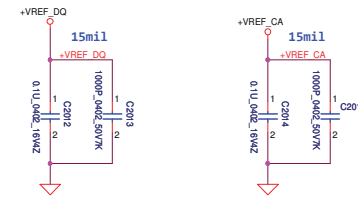
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Issued Date	2011/04/18	Deciphered Date	2015/07/08	Title	FS1r2 Signal Level Shifter	
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Reverse H:9.2mm

DDR8\_SQ0[0..63] 6  
DDR8\_SDM[0..7] 6  
DDR8\_SMA[0..15] 6



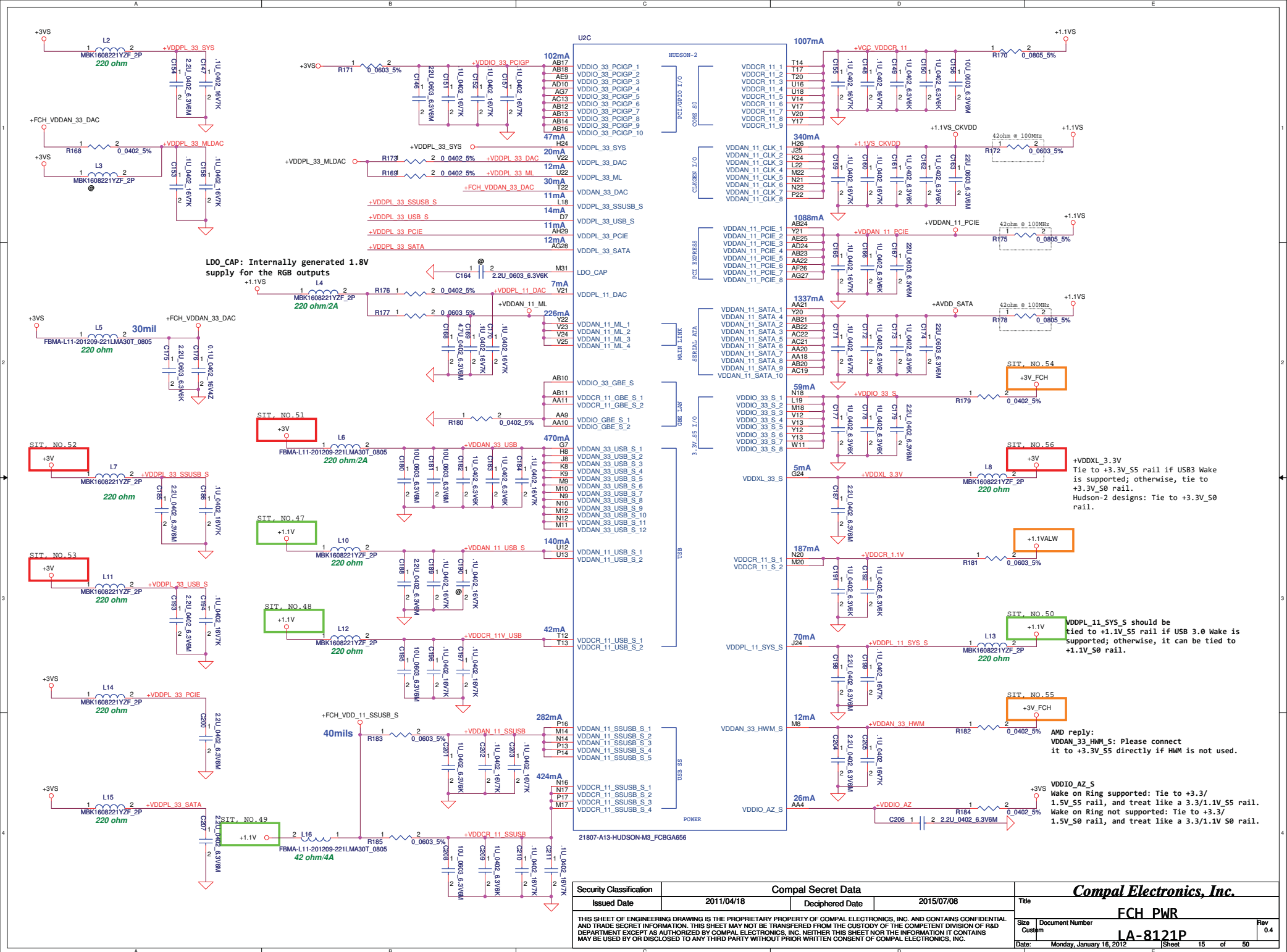
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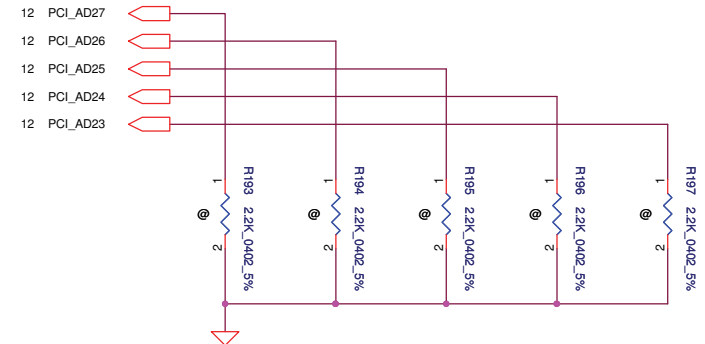
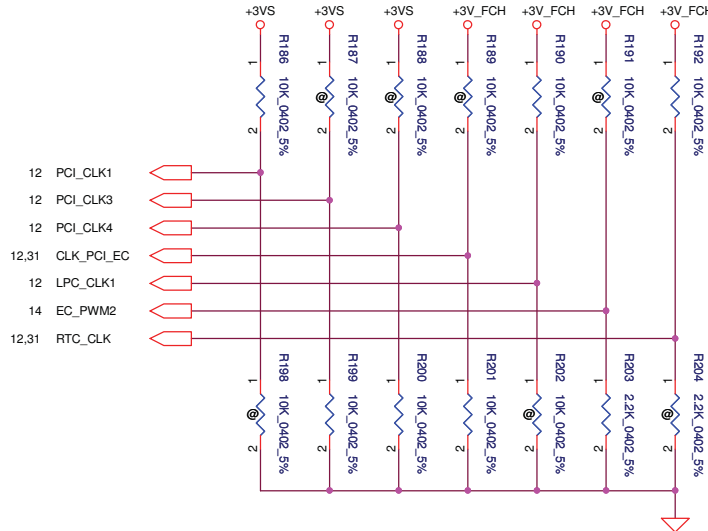
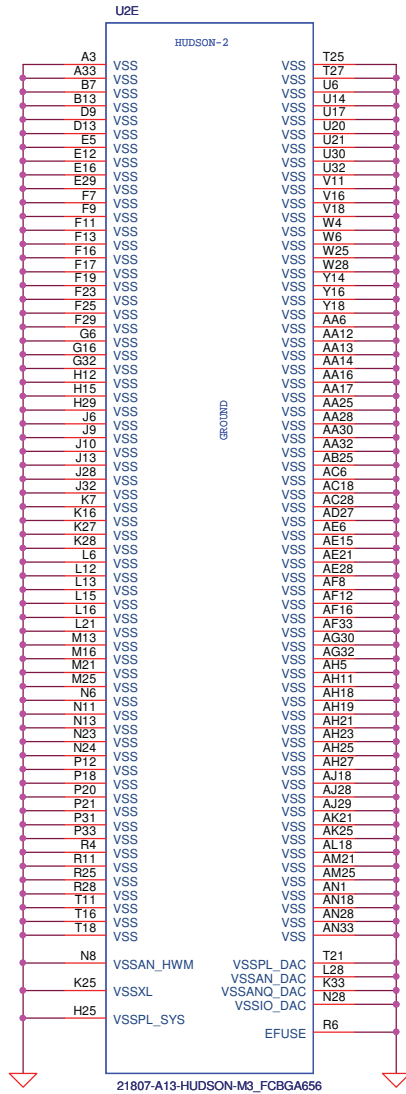
## STRAP PINS

	PCI_CLK1	PCI_CLK3	PCI_CLK4	CLK_PCI_EC	LPC_CLK1	EC_PWM2	RTC_CLK
PULL HIGH	ALLOW PCIE GEN2 DEFAULT	USE DEBUG STRAPS	NON_FUSION CLOCK MODE	EC ENABLED	CLKGEN ENABLED DEFAULT	LPC ROM	S5 PLUS MODE DISABLED DEFAULT
PULL LOW	FORCE PCIE GEN1	IGNORE DEBUG STRAP DEFAULT	FUSION CLOCK MODE DEFAULT	EC DISABLED DEFAULT	CLKGEN DISABLE	SPI ROM DEFAULT	S5 PLUS MODE ENABLED

## DEBUG STRAPS

FCH HAS 15K INTERNAL PU FOR PCI\_AD[27:23]

	PCI_AD27	PCI_AD26	PCI_AD25	PCI_AD24	PCI_AD23
PULL HIGH	USE PCI PLL DEFAULT	DISABLE ILA AUTORUN DEFAULT	USE FC PLL DEFAULT	USE DEFAULT PCIE STRAPS DEFAULT	DISABLE PCI MEM BOOT DEFAULT
PULL LOW	BYPASS PCI PLL	ENABLE ILA AUTORUN	BYPASS FC PLL	USE EEPROM PCIE STRAPS	ENABLE PCI MEM BOOT



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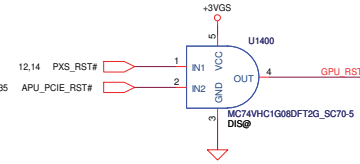
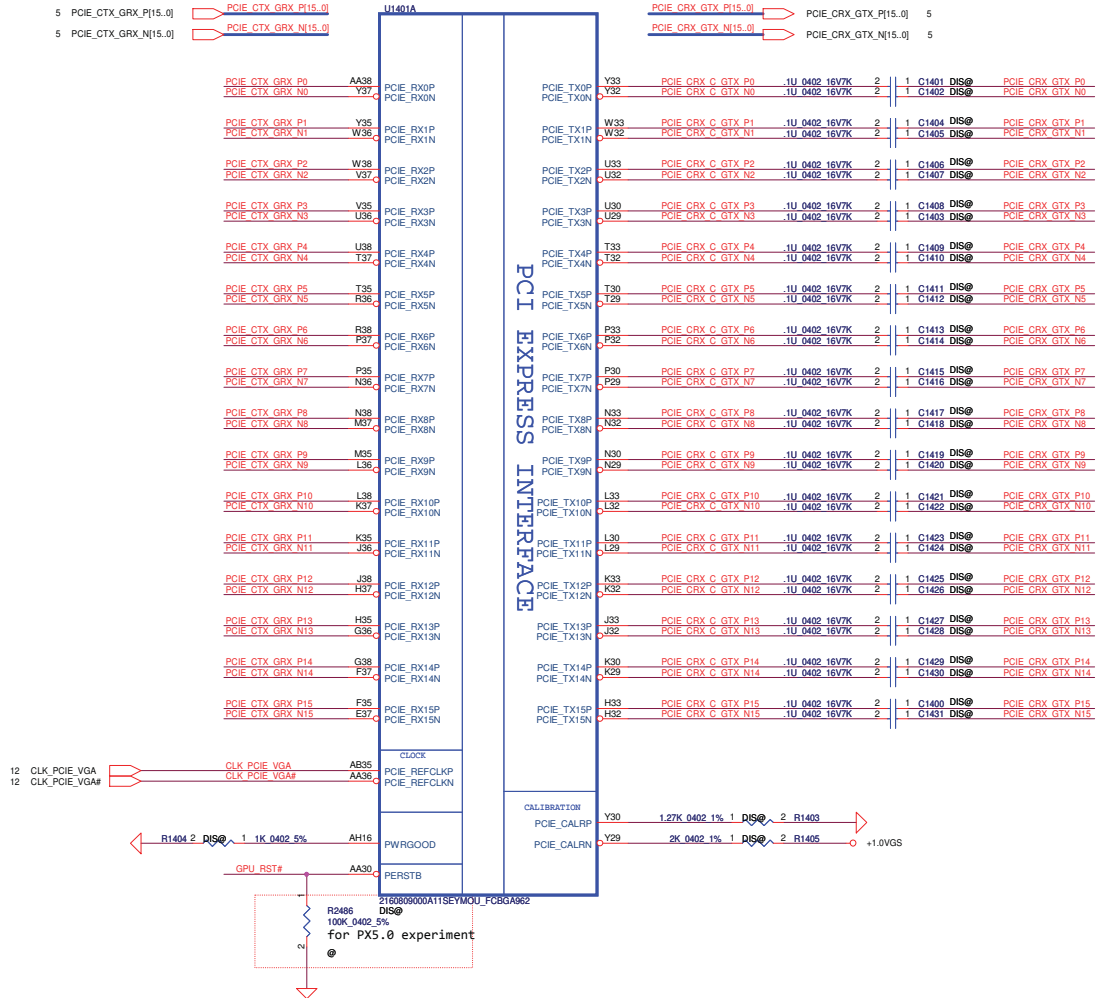
5 PCIE\_CTX\_GRX\_P[15..0]  
5 PCIE\_CTX\_GRX\_N[15..0]

PCIE\_CTX\_GRX\_P[15..0]  
PCIE\_CTX\_GRX\_N[15..0]

PCIE\_CRX\_GTX\_P[15..0]  
PCIE\_CRX\_GTX\_N[15..0]

PCIE\_CRX\_GTX\_P[15..0]  
PCIE\_CRX\_GTX\_N[15..0]

## LVDS Interface

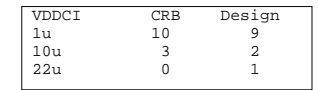


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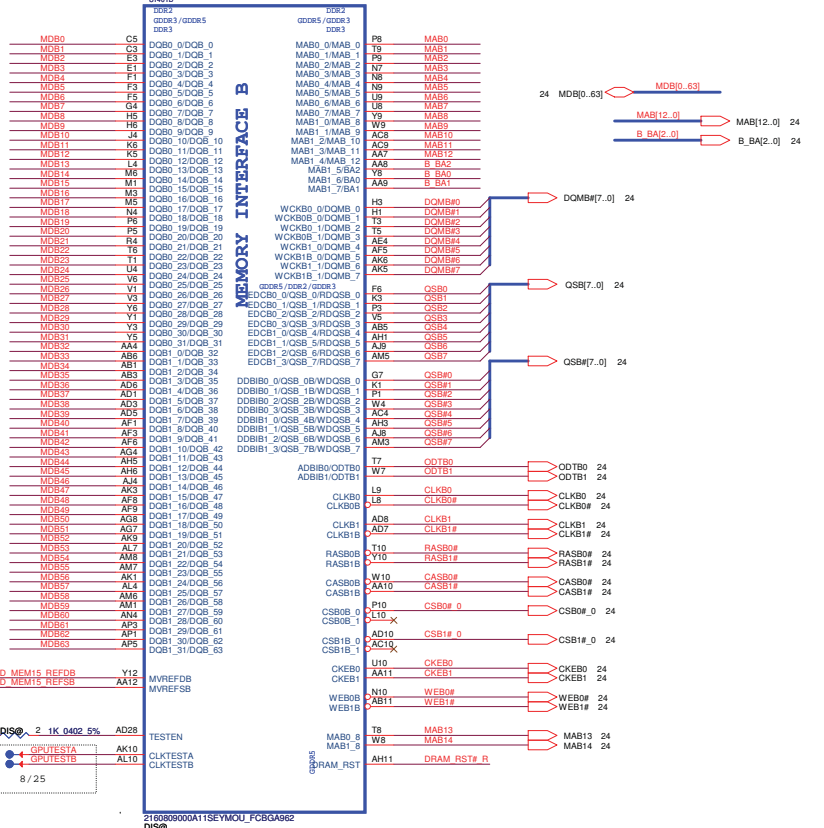
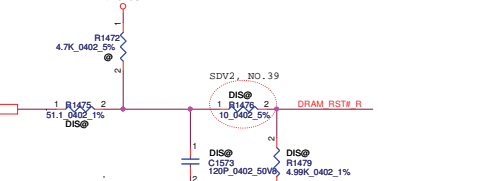
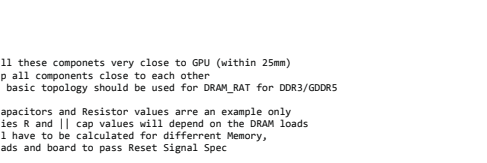
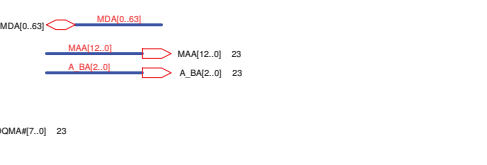
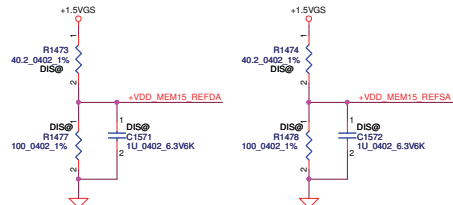




Depending on the performance requirement  
VDDCI and VDDC might require separate regulators with a merge option on PCB  
or VDDCI and VDDC can share one common regulator


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1.5VGS	+VDD MEM15 REFDA	L18	NC_MVREFDA	NC_C
	+VDD MEM15 REFSA	L20		



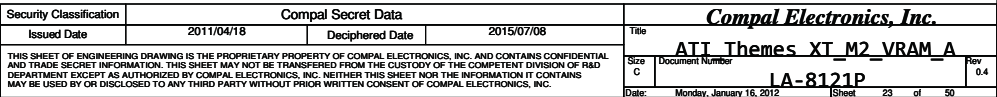
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These Capacitors and Resistor values are an example only  
The series R and || cap values will depend on the DRAM loads  
and will have to be calculated for different Memory,  
DRAM loads and board to pass Reset Signal Spec

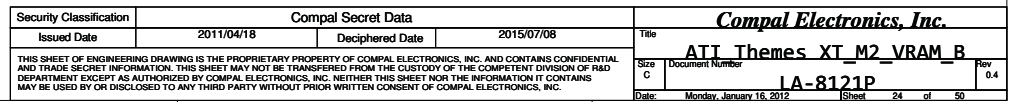
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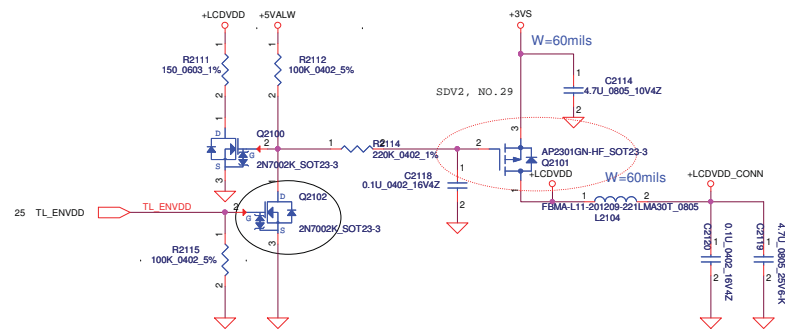


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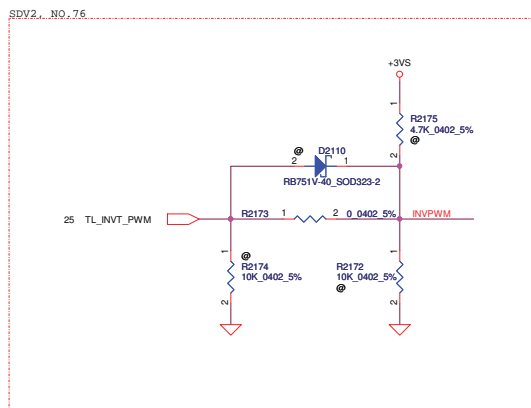
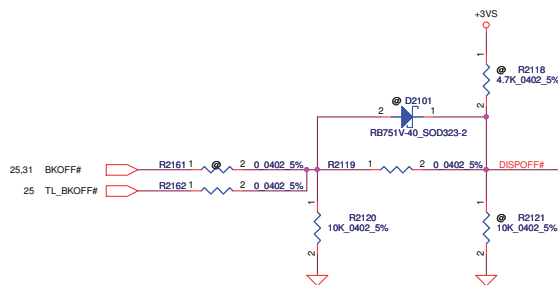




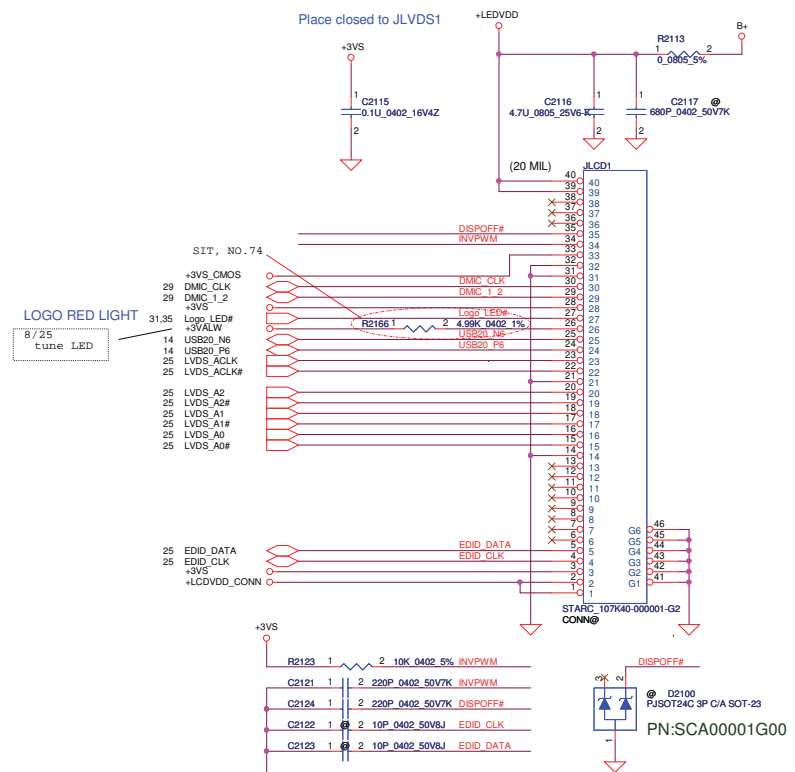
## LCD POWER CIRCUIT



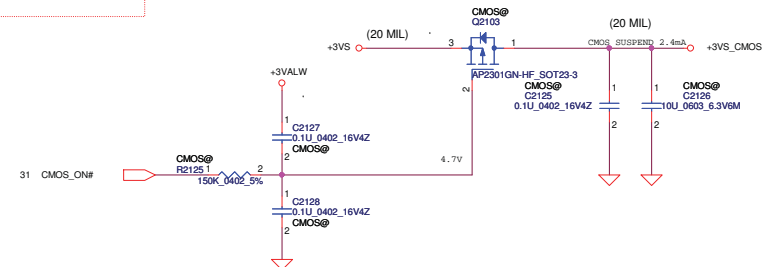
CMOS



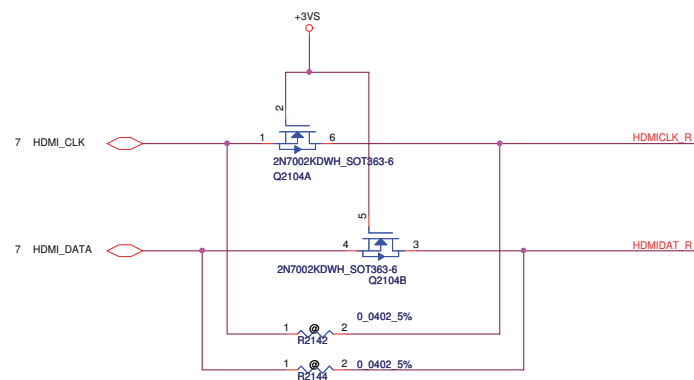
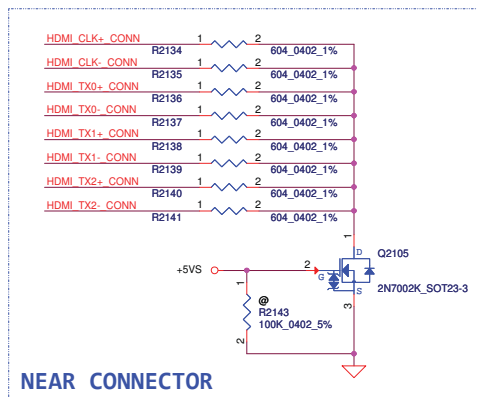
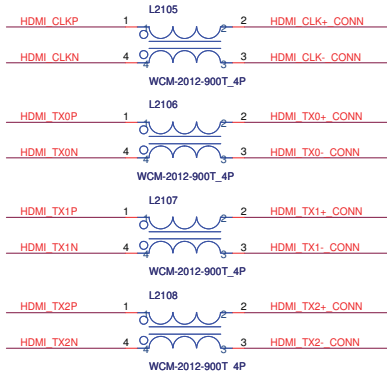
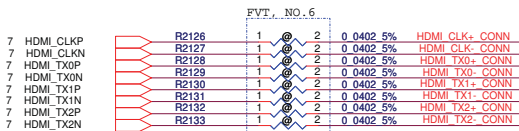
**LCD/LED PANEL Conn.**



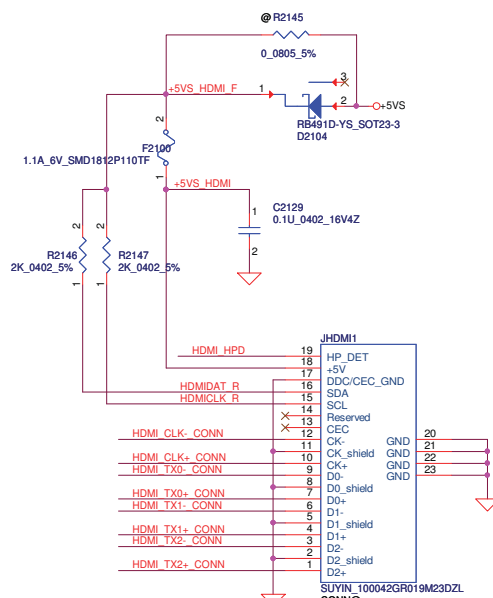
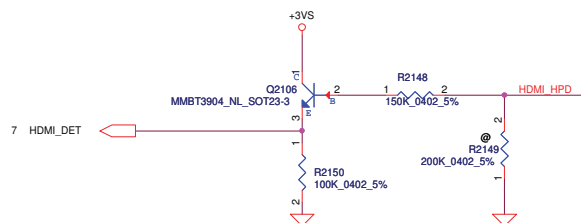
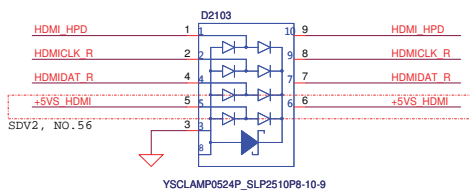
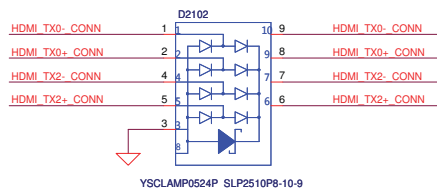
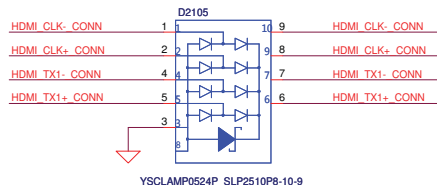
## CMOS Camera Conn



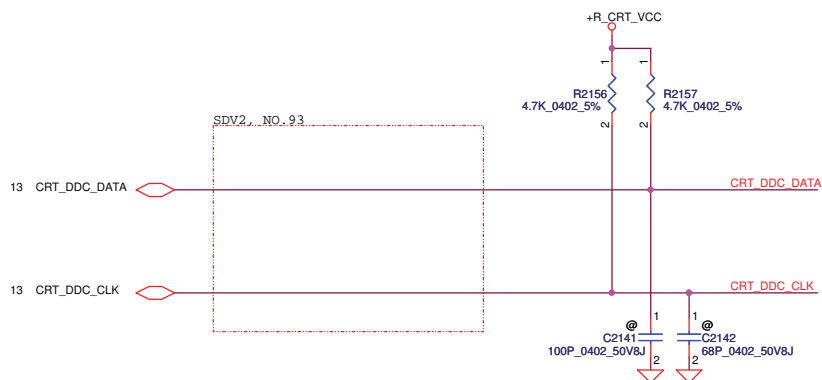
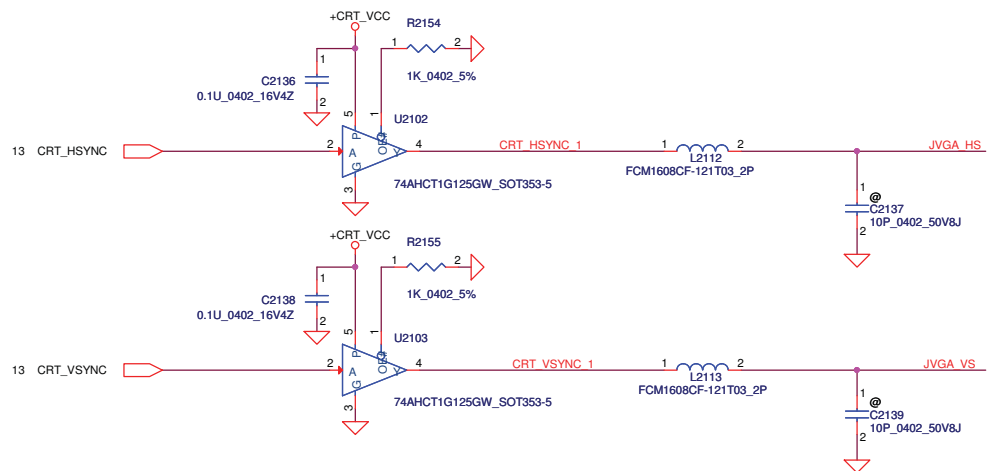
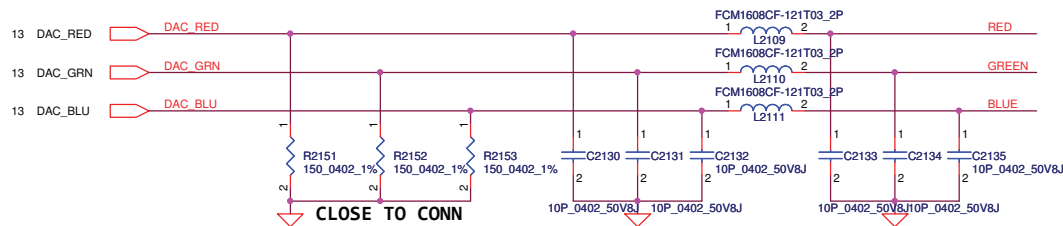
Security Classification		Compal Secret Data		<b>Compal Electronics, Inc.</b> <b>LVDS CONN/CAMERA</b>	
Issued Date	2011/04/18	Deciphered Date	2015/07/08	Title	LVDS CONN/CAMERA LA-8121P
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				Date: Monday, January 16, 2012	Sheet 26 of 50



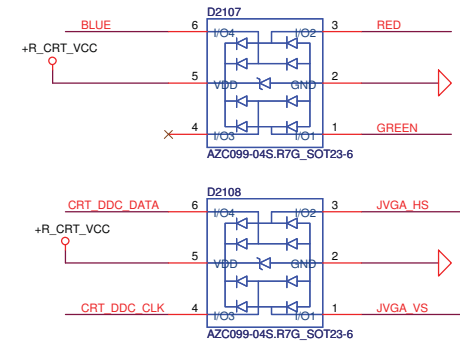
## ESD Request 2011.08.13



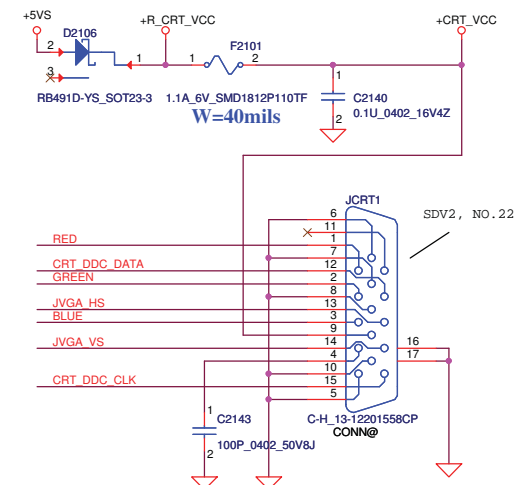
Security Classification		Compal Secret Data		Title	
Issued Date	2011/04/18	Deciphered Date	2015/07/08	HDMI Connector	
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				Custom	0.4
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## ESD Request 2011.08.13



## CRT Connector



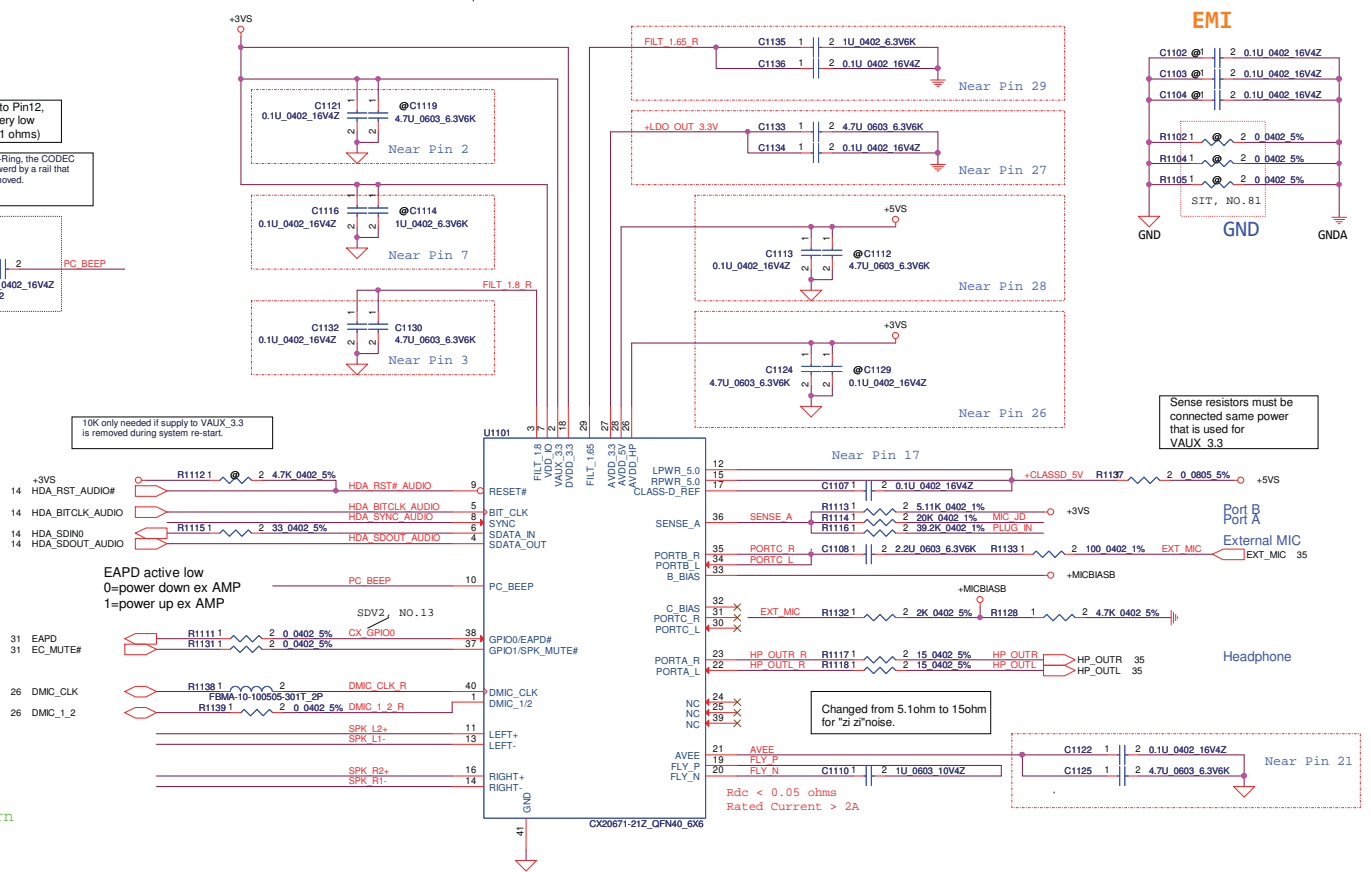
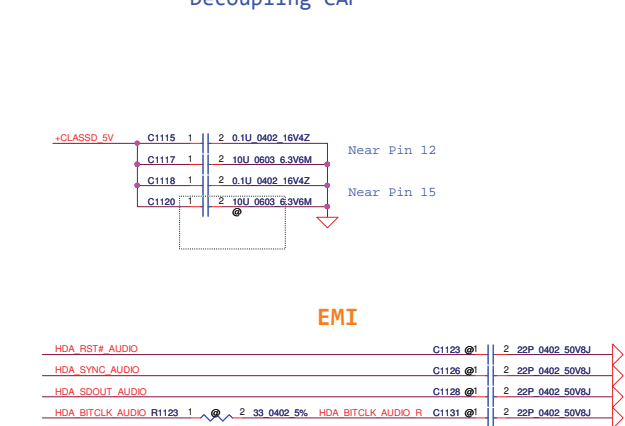
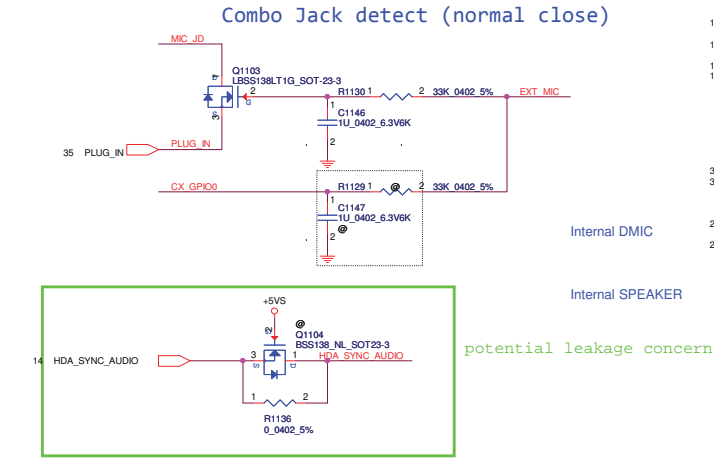
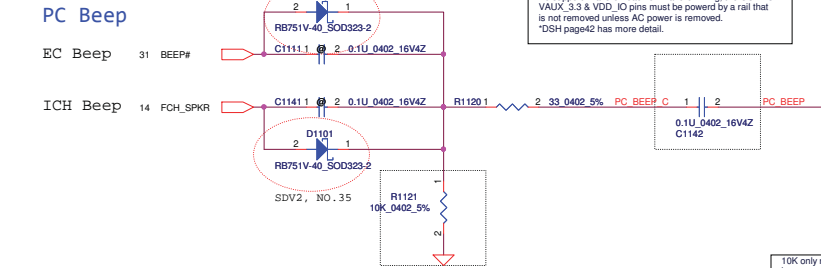
AMD check list update  
20101110

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High Definition Audio Codec SoC  
With Integrated Class-D Stereo  
Amplifier.

An integrated 5 V to 3.3 V Low-dropout  
voltage regulator (LDO).

An integrated 3.3 V to 1.8V Low-dropout  
voltage regulator (LDO).



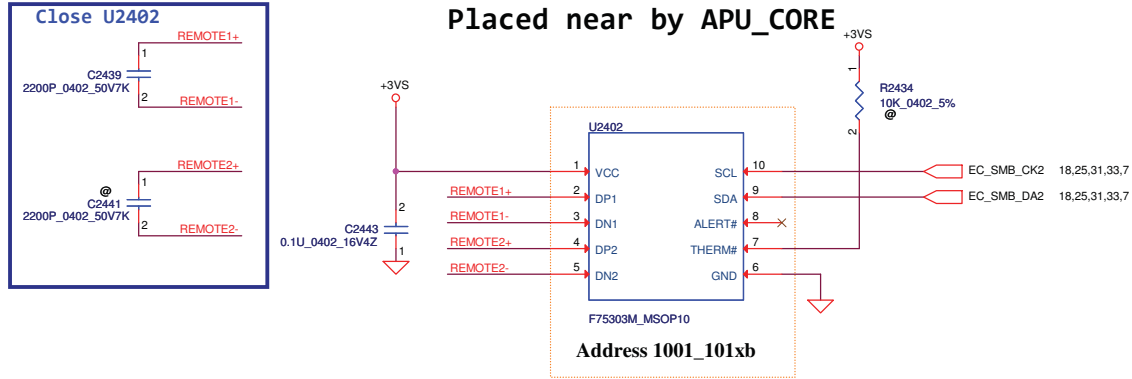
Security Classification		Compal Secret Data				<i>Compal Electronics, Inc.</i>					
Issued Date		2011/04/18		Deciphered Date		2015/07/08		Title			
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								Document Number		Rev	
								Customer		Part	
								LA-8121P			
Date: Monday, January 16, 2012								Sheet 29 of 50			



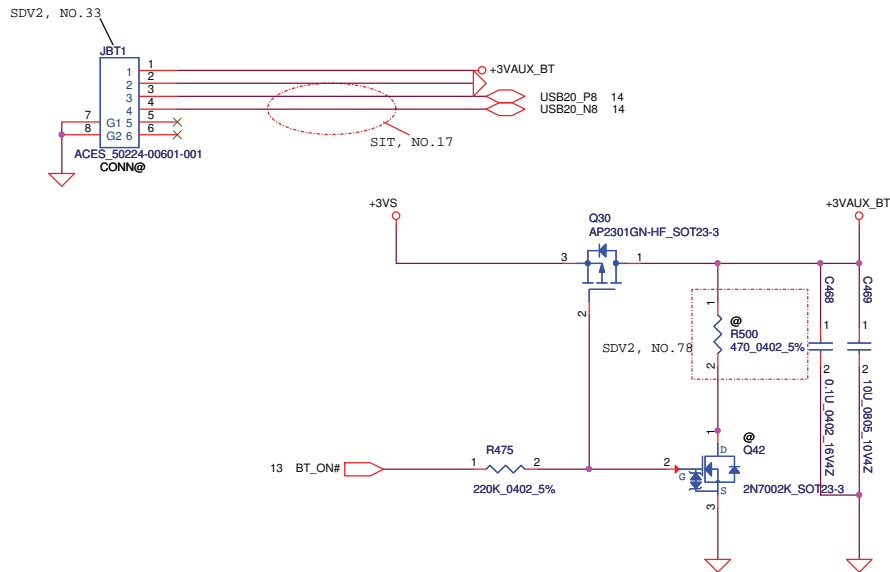




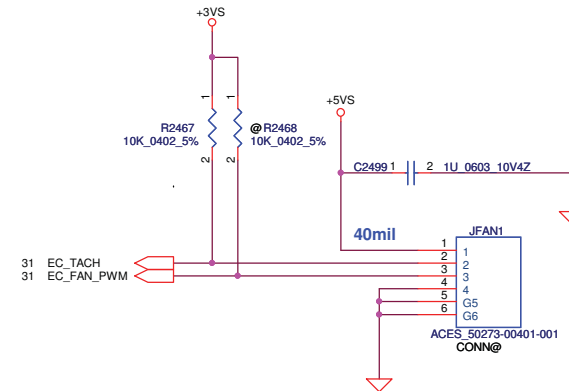
## Fintek Thermal sensor Placed near by APU\_CORE



## BT Connector



## FAN1 Conn



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Issued Date	2011/04/18	Deciphered Date	2015/07/08	Thermal/FAN/BT
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Compal Electronics, Inc.

Thermal/FAN/BT

LA-8121P

Document Number

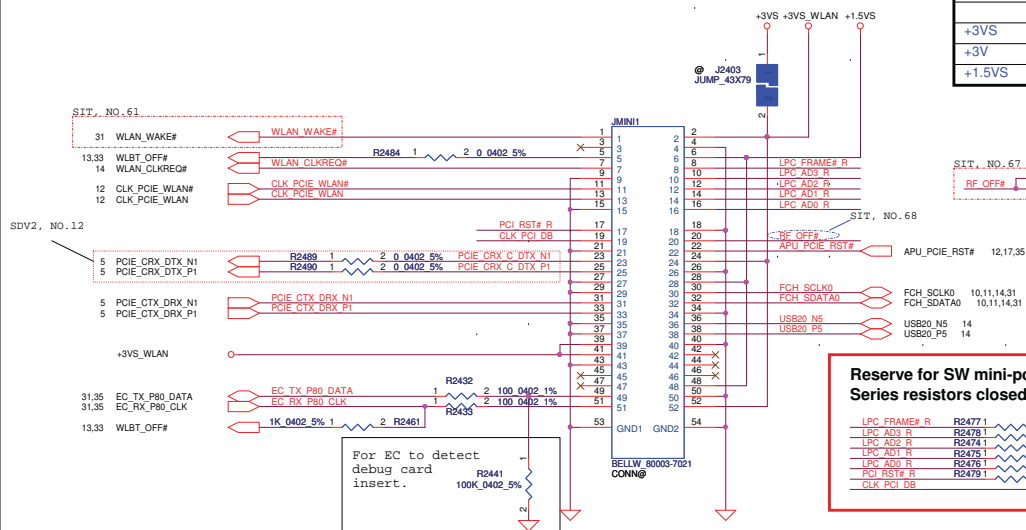
Rev

0.4

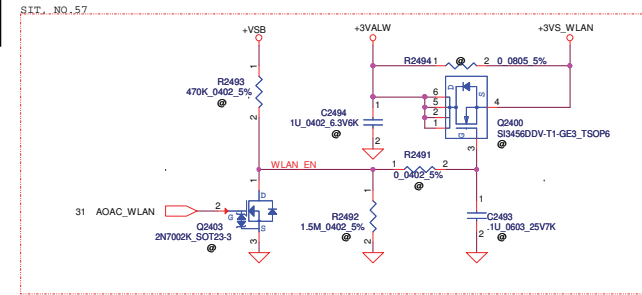
Date: Monday, January 16, 2012

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## WLAN Conn



Power	Primary Power (mA)		Auxiliary Power (mA)
	Peak	Normal	Normal
+3VS	1000	750	
+3V	330	250	250 (wake enable)
+1.5VS	500	375	5 (Not wake enable)



For AOAC assessment

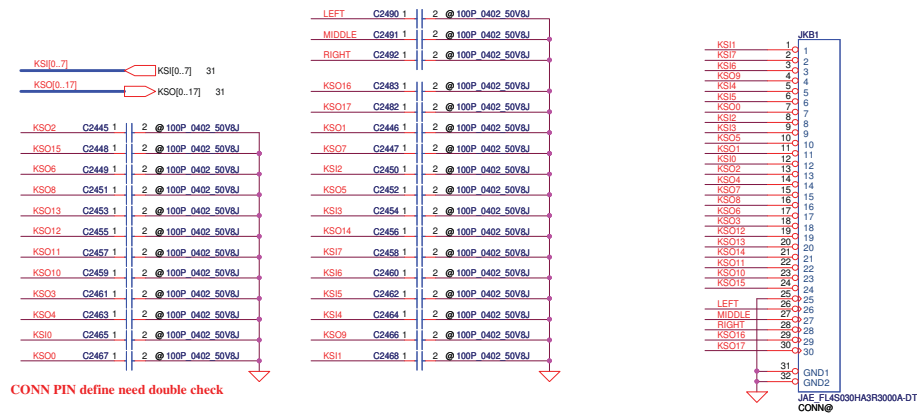
+3VS\_WLAN path:

1. +3VS (default)
2. +3VALW
3. +3VALW + Switch

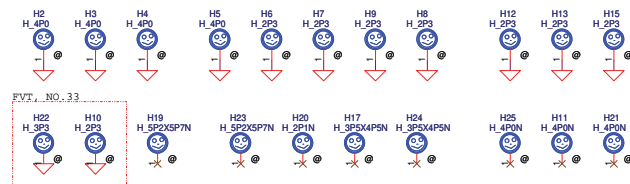
**Reserve for SW mini-pcie debug card.  
Series resistors closed to KBC side.**

Signal	Pin	Direction	Signal	Pin	Direction	Signal	Pin	Direction
LPC FRAME#	R2477	I	LPC FRAME#		O	LPC FRAME#	12,31,35	I
LPC AD3	R2478	I	LPC AD3		O	LPC AD3	12,31,35	I
LPC AD1	R2474	I	LPC AD2		O	LPC AD2	12,31,35	I
LPC AD2	R2475	I	LPC AD1		O	LPC AD1	12,31,35	I
LPC AD0	R2476	I	LPC AD0		O	LPC AD0	12,31,35	I
PCI RST#	R2479	I	APU PCIe RST#		O	CLK_PCI_DB	12,35	I

INT\_KBD Conn.

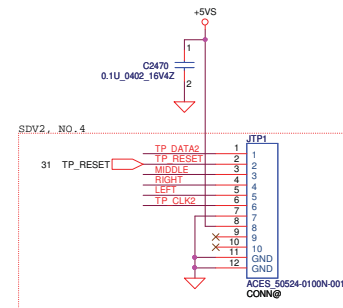


## Screw Holes

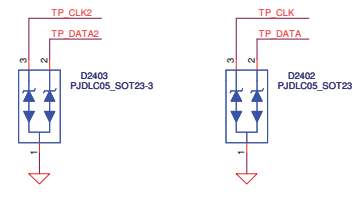


ZZZ3  
LA-8121\_PCE  
DA80000R200

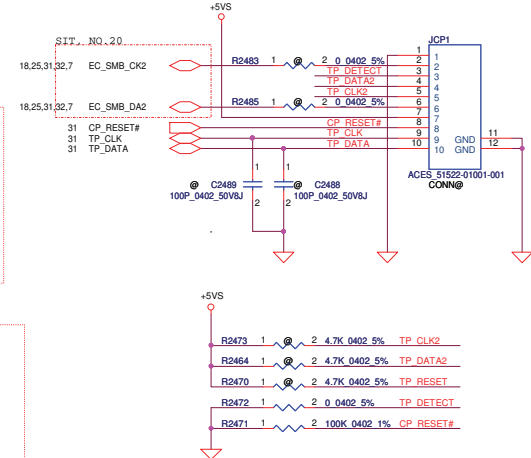
## Track Point Conn



**ESD Request 2011.08.13**



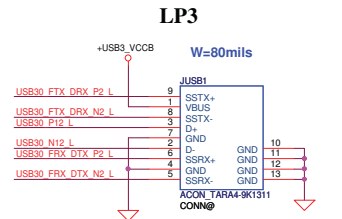
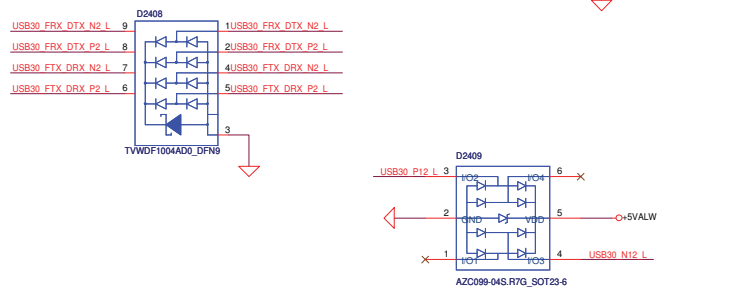
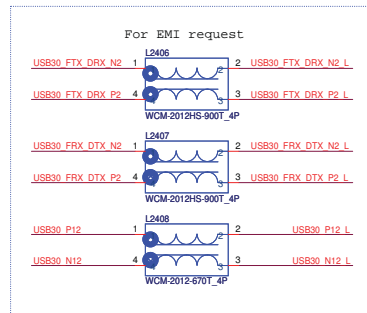
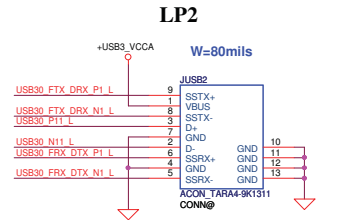
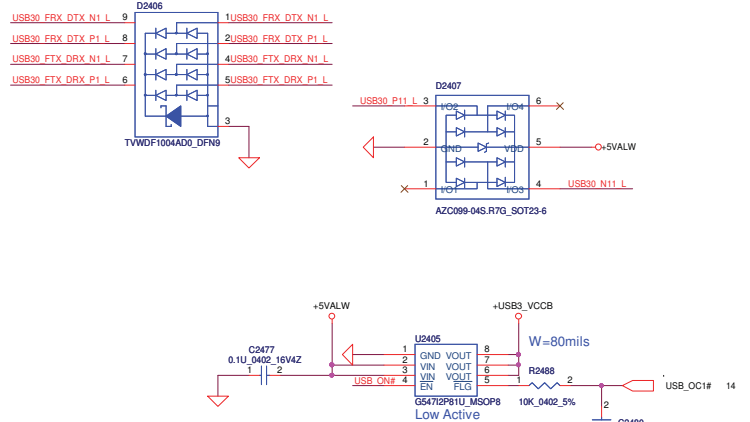
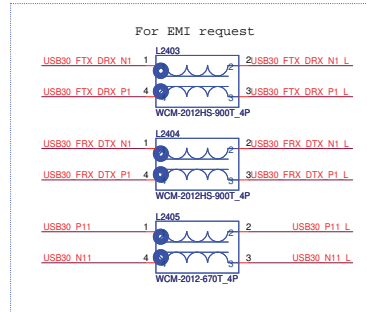
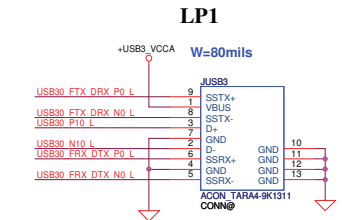
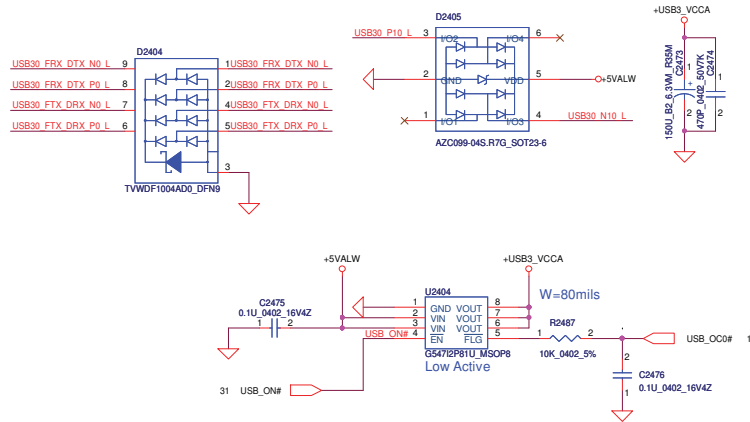
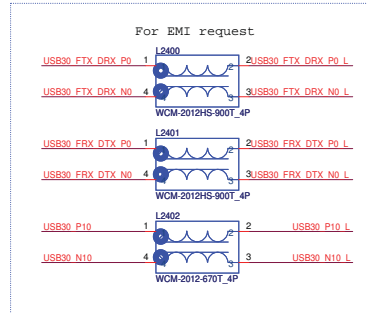
Click pad 10PIN



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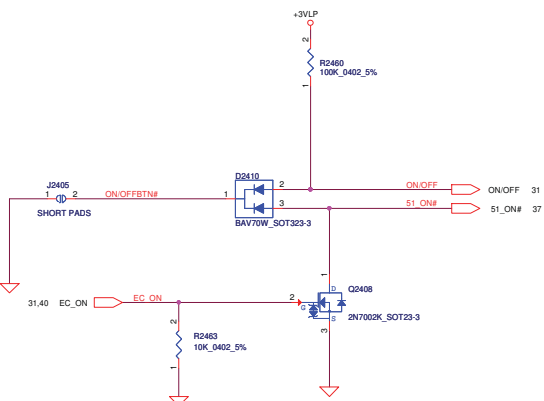
# USB3.0 Conn \*3

FVT., No.5

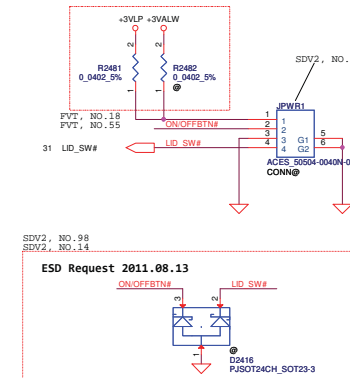


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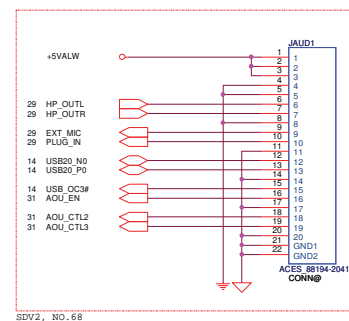
## ON/OFF switch



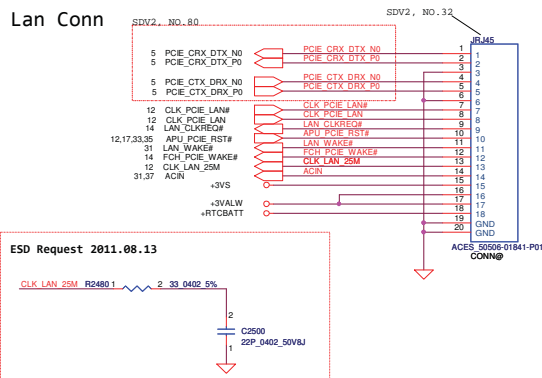
## Power Button Board Conn



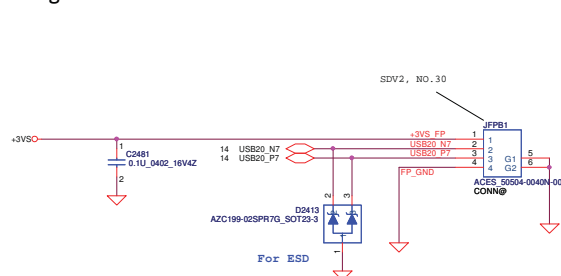
## USB2.0/Audio Jack SB CONN



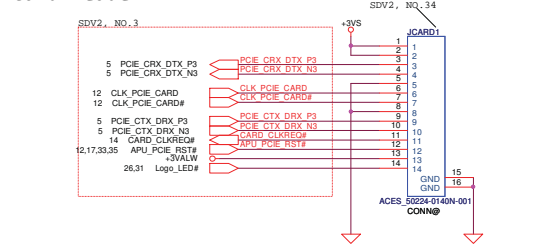
## Lan Conn



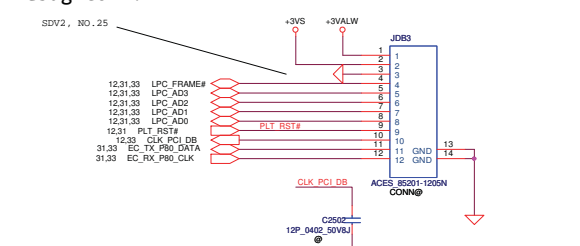
## Finger Printer



## Card Reader



## Debug Conn.



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Title	Sub Board	Size	Document Number
		Customer	LA-8121P
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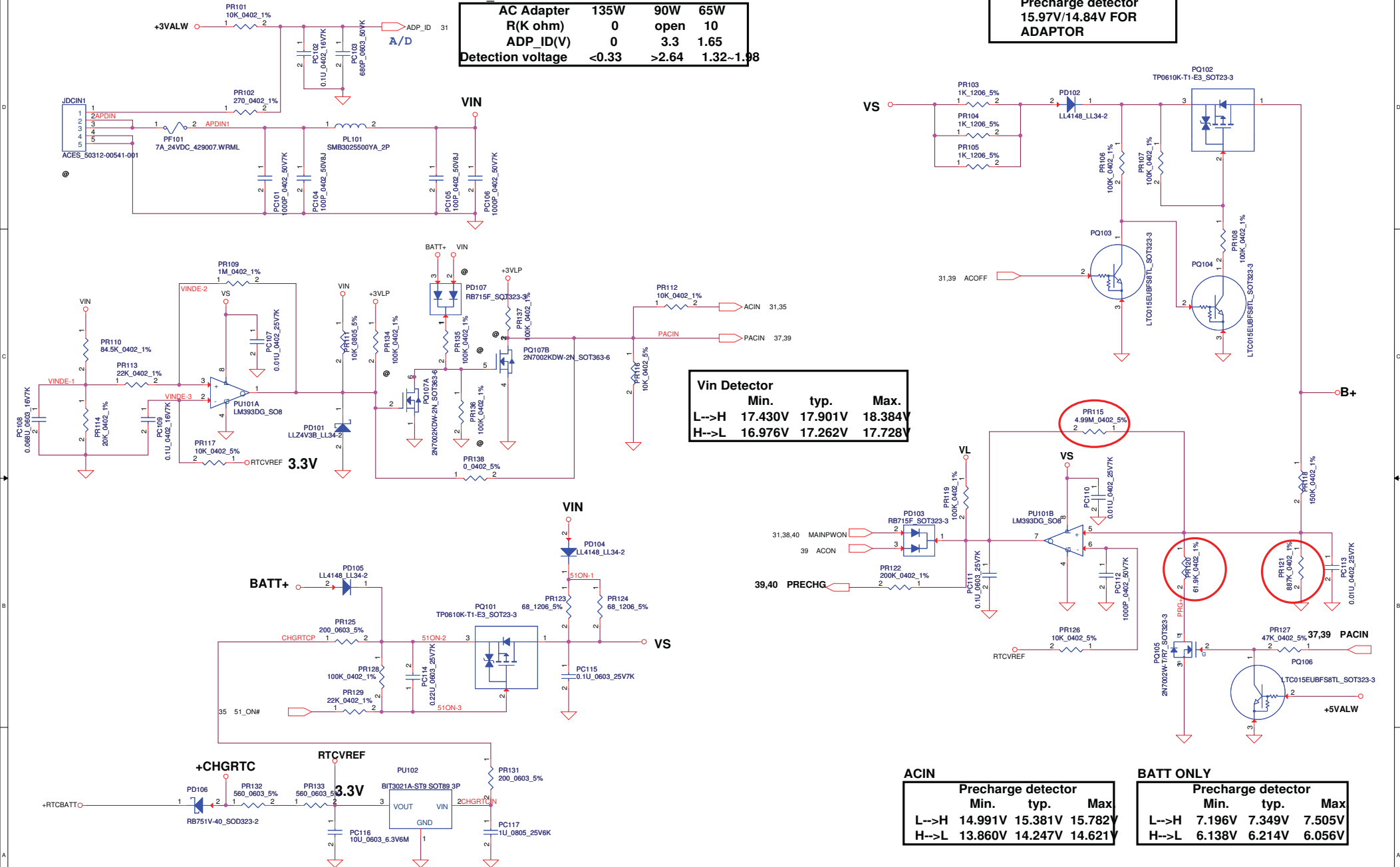




# ADP\_ID

AC Adapter	135W	90W	65W
R(K ohm)	0	open	10
ADP_ID(V)	0	3.3	1.65
Detection voltage	<0.33	>2.64	1.32~1.98

**Precharge detector**  
15.97V/14.84V FOR  
ADAPTOR



<b>Vin Detector</b>	Min.	typ.	Max.
L-->H	17.430V	17.901V	18.384V
H-->L	16.976V	17.262V	17.728V

<b>ACIN</b>	<b>Precharge detector</b>	<b>Min.</b>	<b>typ.</b>	<b>Max.</b>
L-->H	14.991V	15.381V	15.782V	
H-->L	13.860V	14.247V	14.621V	

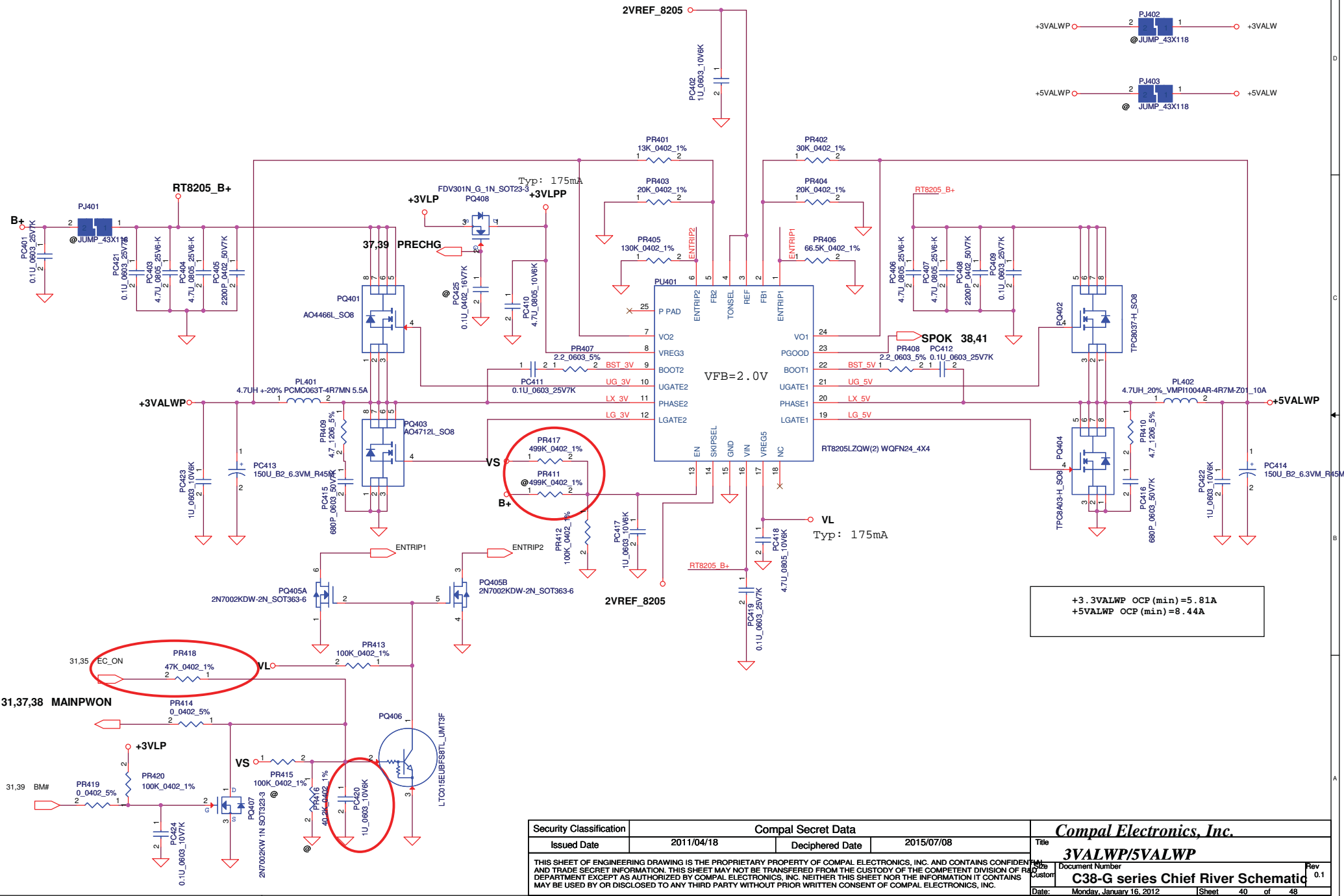
<b>BATT ONLY</b>	<b>Precharge detector</b>	<b>Min.</b>	<b>typ.</b>	<b>Max.</b>
L-->H	7.196V	7.349V	7.505V	
H-->L	6.138V	6.214V	6.056V	

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				Custom
				Document Number
				C38-G series Chief River Schematic <sup>0.1</sup>
				Date
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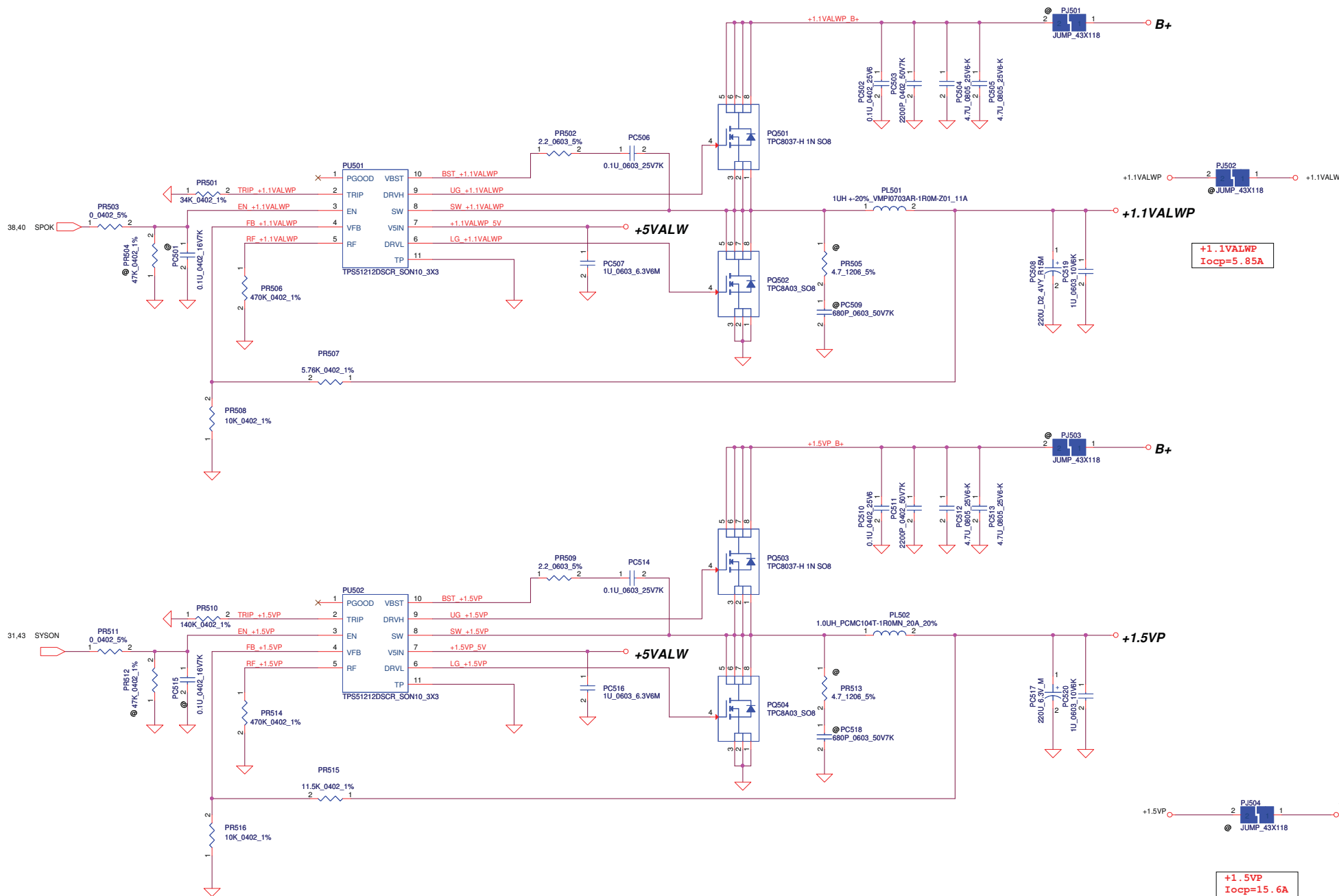




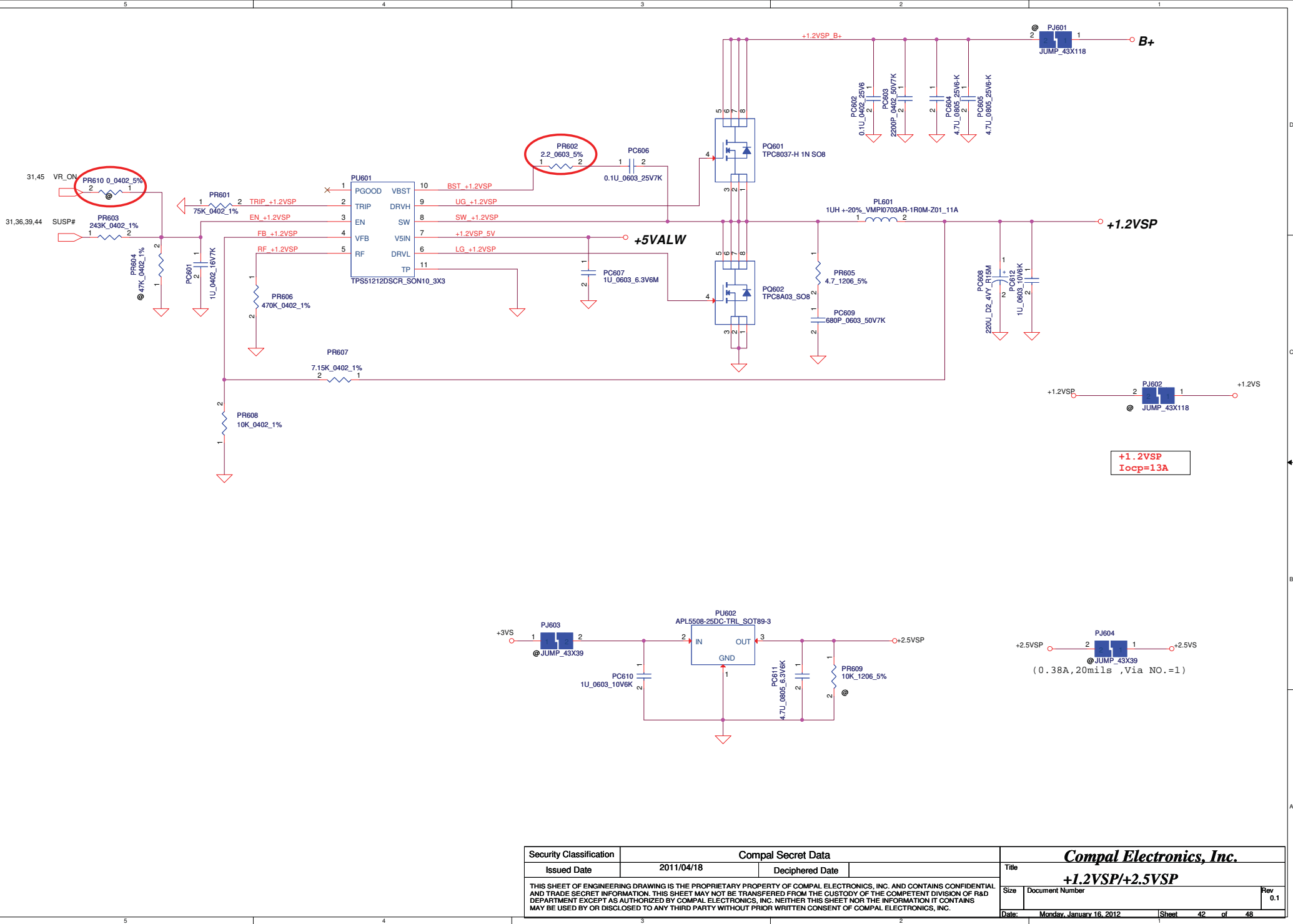
Note:  
Use TPS51125 IC can remove RTC refernece LDO  
Use TPS51427 IC must keep RTC refernece LDO



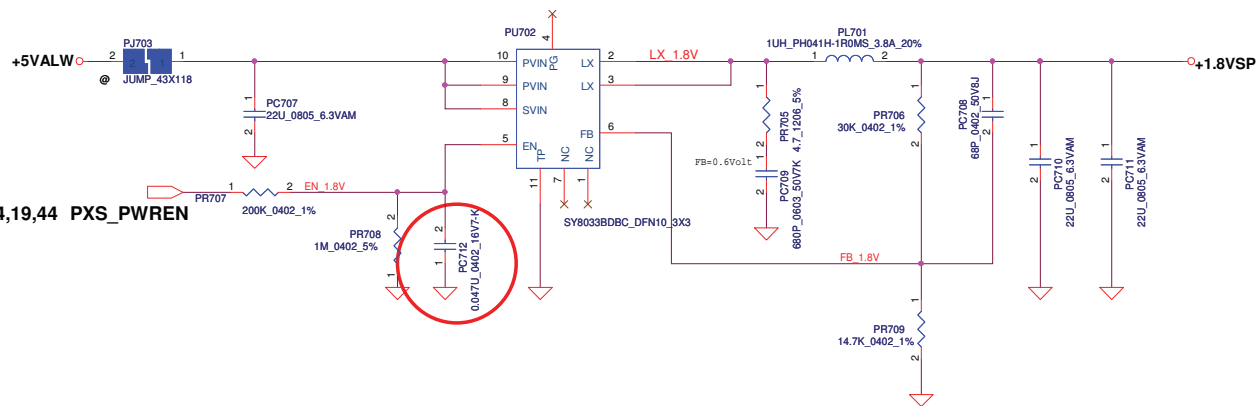
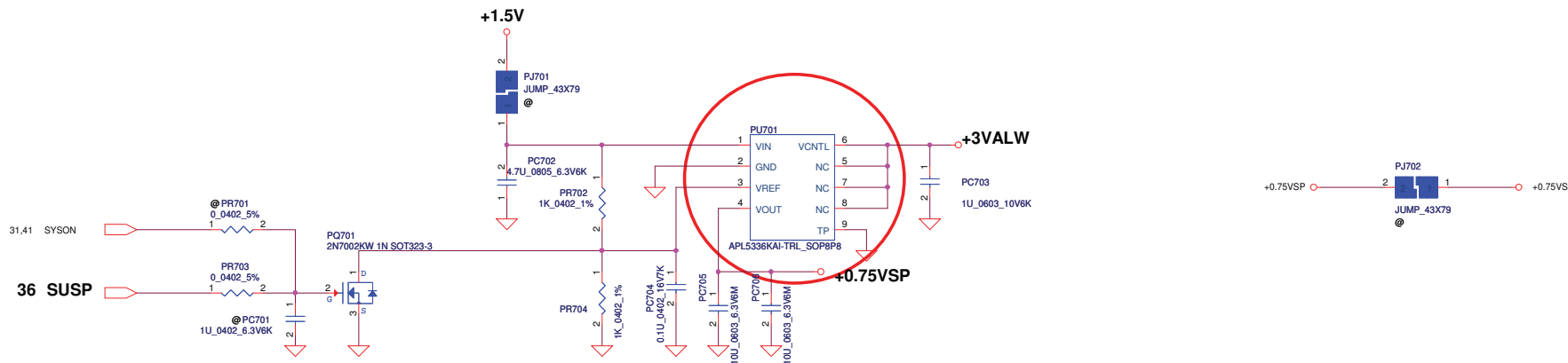
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Issued Date	2011/04/18	Deciphered Date	2015/07/08	Title	3VALWP/5VALWP
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Date: Monday, January 16, 2012				Sheet 43 of 48	

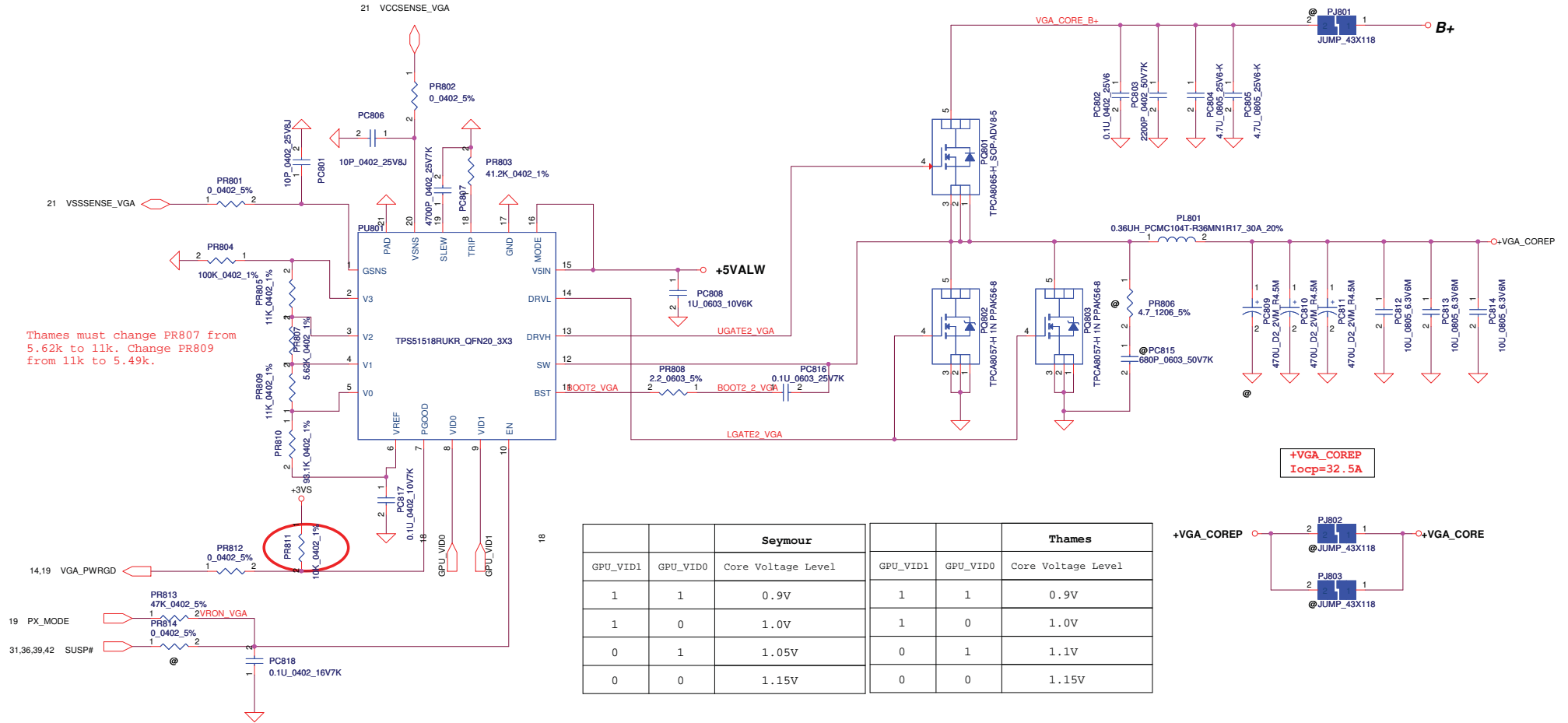
Compal Electronics, Inc.

+0.75VP/+1.8VP

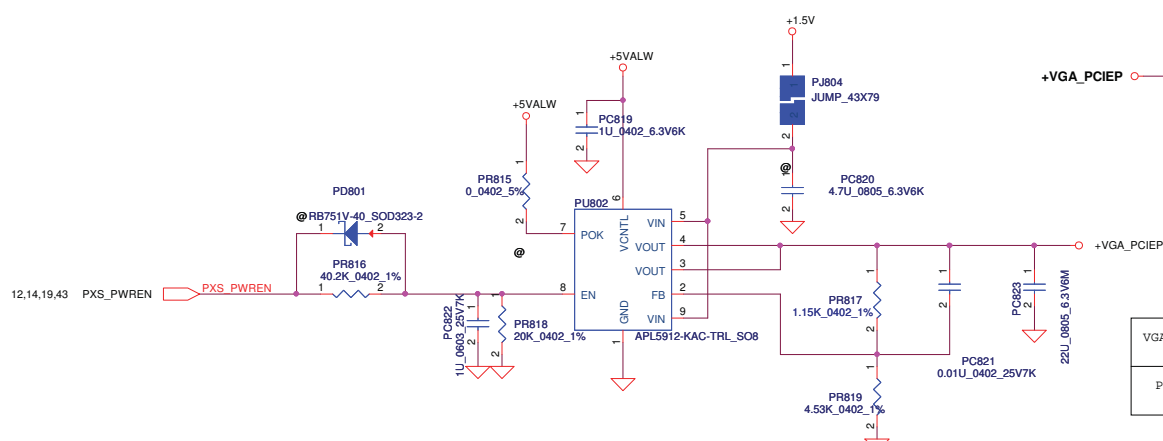
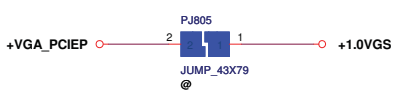
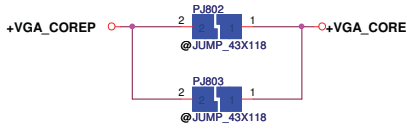
Size Document Number Rev 0.1

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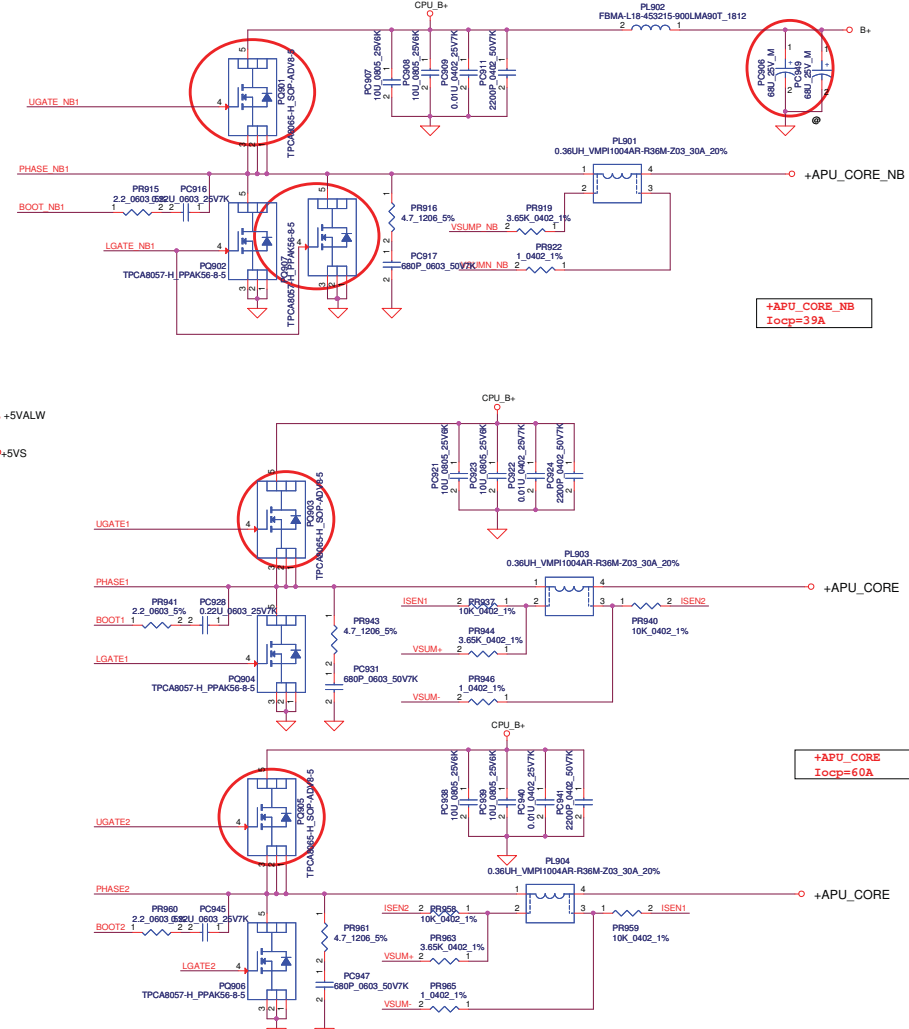


Seymour			Thames		
GPU_VID1	GPU_VID0	Core Voltage Level	GPU_VID1	GPU_VID0	Core Voltage Level
1	1	0.9V	1	1	0.9V
1	0	1.0V	1	0	1.0V
0	1	1.05V	0	1	1.1V
0	0	1.15V	0	0	1.15V

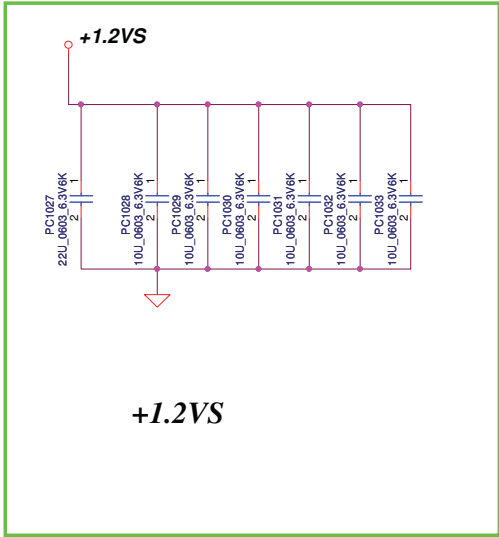
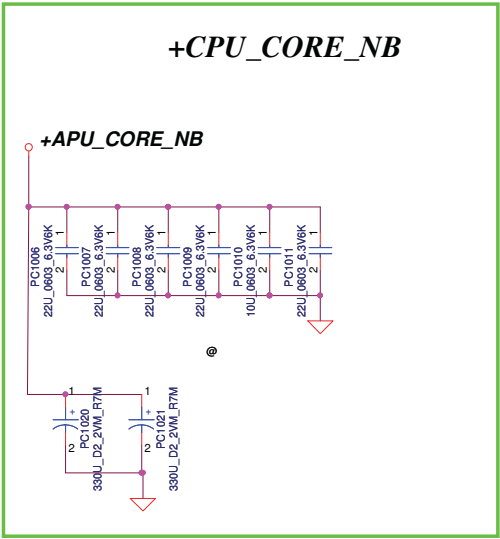
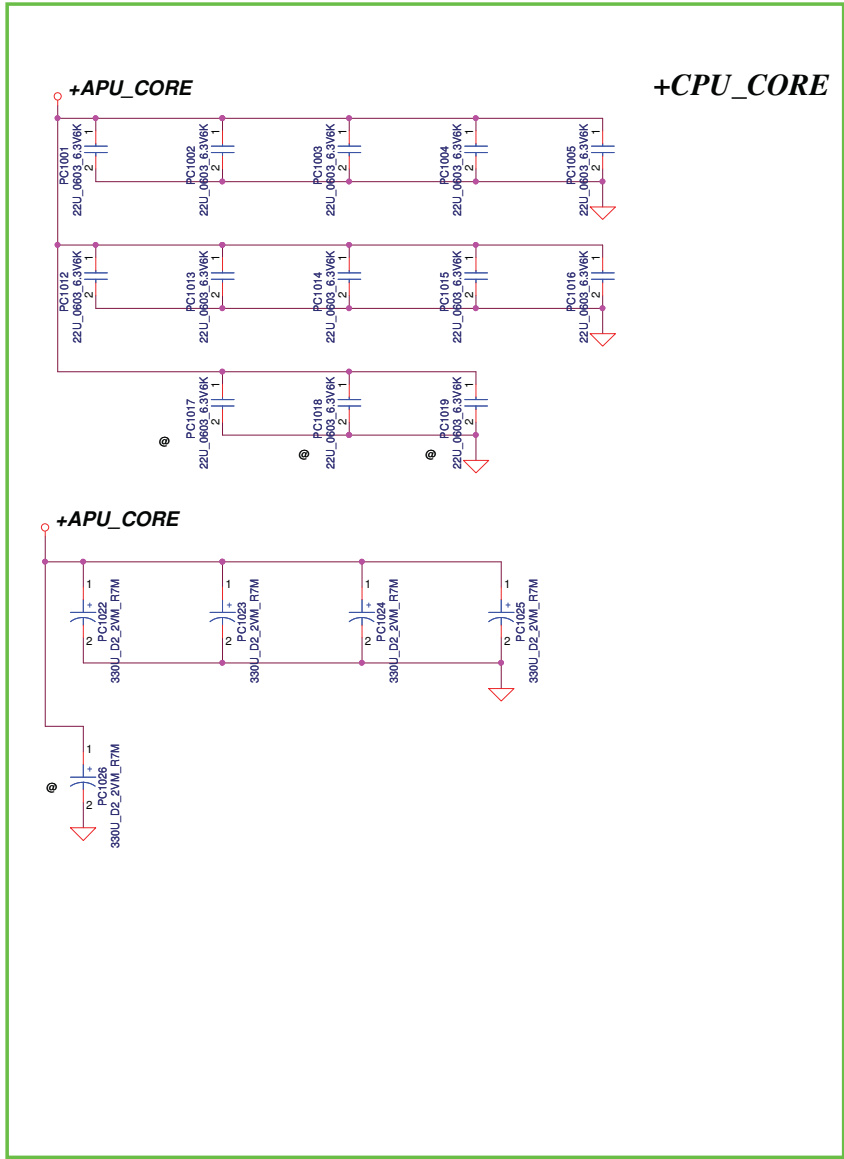


VGA_PCIE	1.0V	1.1 V
PR819	4.53K	3K

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Item	Reason for change	PG#	Modify List	Date	Phase
1					
2					
3					
4					
5					
6					
7					
8					
9					
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11					
12					
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Security Classification	Compal Secret Data			Compal Electronics, Inc.		
Issued Date	2011/04/18	Deciphered Date	2015/07/08	Title	PIR (PWR)	
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				Custom	C38-G series Chief River Schematic	0.1
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Phase	Date	No.	BOM	Sch	Layout	Description
SDV2	2011/09/13	No.1	V			Page29, install R1102, R1104, R1105 for audio noise prevention
	2011/09/14	No.2	V			Page12~16, change FCH P/N from SA000043IC0 to SA000043IG0
	2011/09/16	No.3	V	V		Page35, Swap JCARD1 Pin3,4 to Pin9,10 PCIE TX & RX for CardReader no function issue
	2011/09/16	No.4	V	V		Page33, Modify JTP1 Pin1 to TP_DATA2, JTP1 Pin6 to TP_CLK2 for Click Pad no function issue
	2011/09/17	No.5	V	V		Page30, Modify JH1 Pin18 connect to GND for SATA Gen2
	2011/09/17	No.6	V			Page5~9, Modify U1 to JCPU1
	2011/09/17	No.7	V			Page10~11, SWAP JDIMM1 & JDIMM2
	2011/09/17	No.8	V			Page33, Modify JFP1 to JFPB1,Modify JWLAN1 to JMINI1,Modify JLAN1 to JRJ45
	2011/09/17	No.9	V			Page12, Modify CLRPI to JCMOS1
	2011/09/26	No.10	V			Page31, POP U2201,C2200,R2229 for Security ROM Function not work issue
	2011/09/26	No.11	V			Page14, Modify D1103,D1104 to DIS# for DIS only
	2011/09/28	No.12	V	V	V	Page29, Reserve R2489,R2490 to PCIE_CK2,PCIE_CK1,PCIE_CKX_P0,PCIE_CKX_P1 for PCIE WLAN RX AC Decoupling
	2011/09/28	No.13	V	V	V	Page29, R1111.2 Connect to U1101 Pin38 add net name CX_GPI00 for vendor request
	2011/09/28	No.14	V	V	V	Page35, Add D2416 to replace D2414 for ESD request
	2011/09/28	No.15	V	V	V	Page5~9, Modify JCPU1 Footprint to LOTES_ACA-ZIF-109_722P-A39 for A39 DFX Rule
	2011/09/28	No.16	V	V	V	Page12~16, Modify U2 Footprint to 21807-A1-HUDSON_FCBGA_656P-A39 for A39 DFX Rule
	2011/09/28	No.17	V	V	V	Page17~22, Modify U1401 Footprint to 2160809000A11SEY_FCBGA_962P-A39 for A39 DFX Rule
	2011/09/28	No.18	V	V	V	Page23~24, Modify U1405~U1412 Footprint to K4W1G1646E-HC12_FBGA_96P-A39 for A39 DFX Rule
	2011/09/28	No.19	V	V		Page31, Modify Board ID Table for AMD Build Plan Change
	2011/09/28	No.20	V	V		Page31, Modify R2209 for QALEA FVT1 Build Board IC Mapping
	2011/09/28	No.21	V	V	V	Page28, update JCRT1 Footprint from SUVIN_070546PR01S2002R_15P to C-H_13-12201558CP_15P-T for ME Conn modify
	2011/09/30	No.22				Page14, Update J1401 Footprint for USB Sequence Tuning
	2011/10/03	No.23	V		V	Page14, Add C222~C237 connect to all USB3.0 port near connector for AMD request that about USB Signal Driving
	2011/10/04	No.24	V	V	V	Page35, Add JDB3 Conn for SW Debug request
	2011/10/05	No.25	V	V	V	Page12, Add TP52~TS8 on U2 GPIO input pin for debug
	2011/10/05	No.26	V	V	V	Page13, Add TP59~T61, TP67~T74 on U2 GPIO input pin for debug
	2011/10/05	No.27	V	V	V	Page13, Add TP59~T61, TP67~T74 on U2 GPIO input pin for debug
	2011/10/05	No.28	V	V	V	Page13, Add TP59~T61, TP67~T74 on U2 GPIO input pin for debug
	2011/10/06	No.29	V	V	V	Page26, Q2101 P/N change to SB00007H10 for Component common
	2011/10/06	No.30	V	V	V	Page35, JFPB1 update P/N to SP010002300 for Conn List update
	2011/10/06	No.31	V	V	V	Page35, JFPB1 update P/N to SP010002300 for Conn List update
	2011/10/06	No.32	V	V	V	Page35, JRJ45 update Footprint to ACES_50506-01841-P01_18P-T for Conn List update
	2011/10/06	No.33	V	V	V	Page32, JBT1 update P/N to SP02000TF00 for Conn List update
	2011/10/06	No.34	V	V	V	Page35, JCARD1 update Footprint to ACES_50224-0140N-001_14P-T for Conn List update
	2011/10/07	No.35	V	V	V	Page29, reserve D1101 for Audio Noise issue
	2011/10/11	No.36	V	V	V	Page12, Del TP52~TS8 on U2 GPIO input pin for debug
	2011/10/11	No.37	V	V	V	Page13, Del TP59~T61, TP67~T74 on U2 GPIO input pin for debug
	2011/10/11	No.38	V	V	V	Page14, Add TP62~T93 on U2 GPIO input pin for debug
	2011/10/12	No.39	V			Page22, Replace R1476 P/N From D028100A00 to SD028100A80 for HF Part modify
	2011/10/12	No.40	V			Page19, 30,36, Replace Q1409,Q2309,Q2410 P/N From SBX01244010 to SB00000J700 for HF Part modify
	2011/10/13	No.41	V			Page12, Replace X1 P/N From SJ100003300 to SJ10000EL00 for Sourcer request (No Footprint, Use SJ10000DJ00)
	2011/10/13	No.42	V			Page12, Replace Y1 P/N From SJ132P7KW10 to SJ10000BM00 for Sourcer request
	2011/10/13	No.43	V			Page18, Replace Y1400 P/N From SJ100006800 to SJ10000DY00 for Sourcer request (No Footprint, Use SJ10000DJ00)
	2011/10/13	No.44	V			Page31, Replace Y2200 P/N From SJ132P7KW10 to SJ10000SM00 for Sourcer request
	2011/10/13	No.45	V	V	V	Page31, Modify U2200 Pin107 EC_PXCONTROL to U2200 Pin108 for ABO Common Design
	2011/10/14	No.46	V	V	V	Page31, Add R2235 pull up to +3V3 for PROCHOT#_EC
	2011/10/14	No.47	V	V	V	Page19, Replace Q1401,Q1402,Q1404,Q1405 P/N From SB00000FG00 to SB00000FG10 for Sourcer request
	2011/10/17	No.48	V	V	V	Page26, Add C2144,C2145 1000P Caps connect to DMIC_CLK & DMIC_L_2 for EMI Request(Noise issue)
	2011/10/17	No.49	V	V	V	Page25, Add R2171 connect to LVDS_HPD_R for Vendor Request (Noise Filtering)
	2011/10/17	No.50	V	V	V	Page7,9,27 Replace Q2,Q3,Q8,Q2106 P/N From SB000006A00 to SB000006A10 for HF Part modify
	2011/10/17	No.51	V	V	V	Page14, Del D1103,D1104, Add D1103,D1104 & use EC_CK2 to Control PXS_PWREN ON/OFF Timing for VGA Sequence tuning
	2011/10/17	No.52	V			Page19, Modify C1463,D1400,R1442 BOM Structure from DIS# to PX40# & D1400 use 0_0603_58 for PX50
	2011/10/17	No.53	V			Page7, Modify R65,R69 BOM Structure to @ for Power Leakage issue
	2011/10/17	No.54	V			Page12, Modify R80,R82 value from 0 ohm to 33 ohm for EMI Noise Issue
	2011/10/18	No.55	V	V		Page7,11, Modify instruction: H_PROCHOT#, Turbo_V
	2011/10/18	No.56	V	V	V	Page27, Add Net +5VS_HDMI on D2103 Pin5 & Pin6 for ESD Request
	2011/10/18	No.57	V			Page19, Modify R1454,Q1412,R1450,R1451,R1449,C1470,U1404,C1467,C1468,C1469,C1470 BOM Structure from PX40 to DIS# for PX50 Function workable
	2011/10/19	No.58	V	V	V	Page31, Add Net APU_LMON on U2200 Pin76 for Power Team Request
	2011/10/19	No.59	V	V	V	Page35, Add intersheet of PLT_RST# on debug card
	2011/10/19	No.60	V	V	V	Page25, modify net name: LVDS_HPD_R to LVDS_HPD_C
	2011/10/20	No.61	V	V	V	Page33, Del A0AC circuit for Customer request
	2011/10/20	No.62	V	V	V	Page31, Del A0AC Powe Control Pin WLAN_POWER# for Customer request
	2011/10/20	No.63	V			Page14, Modify USB Signal net name from USB20_[P..N][10..12]_C to USB30_[P..N][10..12]_C for USB30 net name error
	2011/10/21	No.64	V			Page12, Modify R83,R84 value from 0 ohm to 33 ohm for EMI Noise Issue
	2011/10/21	No.65	V			Page31, Modify R2212,R2213 BOM Structure to @ for ENE Suggestion
	2011/10/21	No.66	V	V	V	Page31, Modify U2200 Pin 72 Net Name From AOU_ILIM to SPK_RT_Detect# for Speaker main stream & retail
	2011/10/21	No.67	V	V	V	Page31, Add R2216 pul up to +3VS for SPK_RT_Detect#
	2011/10/21	No.68	V	V	V	Page35, Modify JAUD1 Pin20 Net Name From AOU_ILIM to GND , Pin17 From AOU_CTL1 to GND ,Pin4 From NC to AGNDfor USB Charger Function
	2011/10/21	No.69	V	V	V	Page29, Modify JSPK1 P/N From DC030008W00 to SP02000N000 & Add JSPK1 Pin5 Connect to SPK_RT_Detect#,JSPK1 Pin6 connect to GND for Speaker main stream & retail
	2011/10/21	No.70	V	V	V	Page31, Modify U2200 Pin120 Net Name From AOU_CTL1 to NC for USB Charger Function1
	2011/10/24	No.71	V	V	V	Page29, reserve D1102 for Audio Noise issue
	2011/10/24	No.72	V			Page35, Modify D2415 BOM Structure to POP for ESD Request
	2011/10/24	No.73	V			Page33, Modify D2402,D2403 BOM Structure to POP for ESD Request
	2011/10/24	No.74	V			Page34, Modify D2402,D2403 BOM Structure to POP for ESD Request
	2011/10/24	No.75	V	V	V	Page31, Modify R2235 BOM Structure to @ for H_PROCHOT#_EC
	2011/10/24	No.76	V	V	V	Page26, Del R2116,R2117, Add R2172-R2176 & Reverse D2110 for PWM Power Leakage issue
	2011/10/24	No.77	V	V	V	Page30, Del C2404,Reserve C2471,C2405 for Intel Circuit Common
	2011/10/24	No.78	V			Page32, Modify R500 BOM Structure to @ for BOM Error
	2011/10/24	No.79	V	V	V	Page31, Del R2223~R2229, Q2200 to update Security ROM Circuit for Intel Circuit Common
	2011/10/24	No.80	V	V	V	Page35, Swap JRJ45 PCIE_CRX_DTX_P0 to PCIE_CRX_DTX_N0, PCIE_CTX_DRX_P0 to PCIE_CTX_DRX_N0 For LAN Board Common
	2011/10/24	No.81	V	V	V	Page35, Del R2462 to update Power OK circuit for Intel Circuit Common
	2011/10/24	No.82	V	V	V	Page36, Del R2300, R2310, C2312, R2317 update Power OK circuit for Intel Circuit Common
	2011/10/24	No.83	V			Page31, Modify R2235 BOM Structure to @ for H_PROCHOT#_EC
	2011/10/24	No.84	V			Page34, Modify D2404,D2406,D2408 P/N From SC300001D00 to SC300002800 for ESD Request
	2011/10/24	No.85	V			Page34, Modify D2404~D2409,L2400~L2408 BOM Structure from @ to POP for EMC Request
	2011/10/24	No.86	V			Page27, Modify L2105~L2108 BOM Structure from @ to POP for EMI Request
	2011/10/24	No.87	V			Page302, Modify L2402,L2405,L2408 P/N From SC300000I00 to SM070000K00 for ESD Request (Footprint SM070000I00)
	2011/10/24	No.88	V			Page34, Modify L2403, L2404, L2400, L2401, L2406, L2407 P/N from SC300000I00 to SM070001S00 for ESD Request
	2011/10/24	No.89	V			Page27, Modify D2102,D2103,D2105 P/N From SC300001Y00 to SC300002C00 for ESD Request
	2011/10/24	No.90	V			Page35, Modify D2413 P/N from SC050001600 to SC0A0001000 for ESD Request
	2011/10/25	No.91	V	V	V	Page29, Modify JSPK1 P/N From SP02000N000 to SC300008W00 For LD Requirement
	2011/10/25	No.92	V	V	V	Page29, Add R1140 connect to SPK_RT_Detect# to GND for Speaker Verify
	2011/10/25	No.93	V	V	V	Page28, Del Q2412 with CRT_DDC_DATA & CRT_DDC_CLK for AMD Design Guide Require
	2011/10/26	No.94	V	V	V	Page26, Del D1122,R2124 with EDID_DATA & EDID_CLK pull up for Duplicate Pull up error
	2011/10/26	No.95	V	V	V	Page26, Modify R2174 BOM Structure to @ for BOM Error
	2011/10/26	No.96	V	V	V	Page25, Reserve R2116, R2117 to Connect from CSCL & CSCA to EC_SMB_DA2 & EC_SMB_CK2 for Power Leakage issue
	2011/10/26	No.97	V			Page29, Modify D1101, D1102 BOM Structure From @ to POP for Audio Noise issue
	2011/10/27	No.98	V	V	V	Page35, Modify D2416 P/N From SC300001000 to SC0A0001000 for ESD Request
	2011/10/27	No.99	V	V	V	Page29, Modify C1111 ,C1114 BOM Structure From POP to @ for Audio Noise issue

Phase	Date	No.	BOM	Sch	Layout	Description
FVT	2011/11/14	No.1	V			Page17~24, Modify U1401 P/N From SA000047H00 to SA000047H50 for GPU Version update
	2011/11/14	No.2	V			Page36, Modify R2305 P/N From SD028200280 (20K_0402_5K) to SD028150380 (150K_0402_5K) for Power Consumption & Power Sequence tuning
	2011/11/14	No.3	V			Page36, Modify R2304 P/N From SD028470280 (47K_0402_5K) to SD028470380 (470K_0402_5K) for Power Consumption & Power Sequence tuning
	2011/11/14	No.4	V			Page36, Modify R2315 P/N From SD028750280 (75K_0402_5K) to SD028220380 (220K_0402_5K) for Power Consumption & Power Sequence tuning
	2011/11/14	No.5	V			Page34, Modify R2442~R2459 BOM Structure From POP to @ for EMI Request
	2011/11/14	No.6	V			Page27, Modify R2126~R2133 BOM Structure From POP to @ for EMI Request
	2011/11/14	No.7	V	V	V	Page14, Replace C222~C237 to R216~R231 on all usb port signal for AMD Design checklist update (USB no function issue)
	2011/11/14	No.8	V	V	V	Page19, Add R1461 to connect PXS_PWREN, RUNPWROK for PXS Power Enable
	2011/11/14	No.9	V	V	V	Page14, Remove R230~R231 on all usb port signal for AMD Design checklist update (USB no function issue)
	2011/11/15	No.10	V	V	V	Page35, Remove D2415 for ESD Request
	2011/11/21	No.11	V	V		Page30, Reserve R2411, C2421 for G Sensor Vendor Suggestion
	2011/11/21	No.12	V	V	V	Page31, Add J2200, J2201 to improve EC Power Source +3VLP or +3VALW to +3VALW_EC Power Source Option and modify +3VALW Net Name to +3VALW_EC for Lenovo S4 Lid Function
	2011/11/21	No.13	V			Page31, Update Borad ID table for FVT Phase
	2011/11/21	No.14	V	V		Page31, Modify R2209 From 8.2K to 18K for FVT BRDID update
	2011/11/21	No.15	V			Page30, C2417 BOM Change from 10U (SE000005T80) to 10K (SD013100280) for G Sensor Vendor Suggestion
	2011/11/21	No.16	V	V	V	Page16, Add R2191, R2322, C2317, C2318, C2319, Q2314 for +3V_FCH Power Control
	2011/11/21	No.17	V	V	V	Page31, U2200 Pin70 Add FCH_PWR_EN# for +3V_FCH Power Control
	2011/11/22	No.18	V	V	V	Page35, Add R2481 Pull up to +3VLP & Reserve R2482 Pull up to +3VALW for Lenovo S4 LID Function
	2011/11/22	No.19	V			Page18, Y1400 P/N From SJ10000DY00 to SJ10000CV00 for BOM Change
	2011/11/22	No.20	V			Page12, X1 P/N From SJ10000EL00 to SJ10000CX00 for BOM Change
	2011/11/22	No.21	V	V	V	Page25, Modify R2117 connect to TL_DATA & R2116 connect to TL_CLK, Two signals connect to R2177, R2178 pull up to +3VS for LVDS Translator EEPROM Reserve
	2011/11/22	No.22	V	V	V	Page31, Modify U2200 Pin86 EAPD to TL_DATA & Add U2200 Pin85 TL_CLK for LVDS Translator EEPROM Reserve Function
	2011/11/22	No.23	V	V	V	Page31, Add U2200 Pin26 EAPD_R for LVDS Translator EEPROM Reserve Function
	2011/11/22	No.24	V	V	V	Page31, Add R2223 & R2224 to option EAPD GPIO Output singal from Pin26 (EAPD_R) or Pin86 (TL_DATA) for LVDS Translator EEPROM Reserve Function
	2011/11/23	No.25	V	V	V	Page14, Del R216~R229 for USB2.0 Signals tuning circuit remove
	2011/11/23	No.26	V	V	V	Page14, Reserve R230~R234 & C222~C226 with USB2.0 N signals port 0,6,10,11,12 for AMD Suggestion
	2011/11/24	No.27	V	V	V	Page36, Del R2321, R2322, C2317, C2318, C2319, Q2314 for +3V_FCH Power Control
	2011/11/24	No.28	V	V	V	Page31, U2200 Pin70 Del FCH_PWR_EN# for +3V_FCH Power Control
	2011/11/24	No.29	V	V		Page29, Modify JSPK1 P/N from DC030008W00 to DC030009100 for ME Connector List update
	2011/11/24	No.30	V	V	V	Page31, U2200 Pin127 Add VSB_ON & Reserve R2226 for +VSB Power Control
	2011/11/25	No.31	V	V	V	Page31, Modify R2217, R2218 Power Source from +3VS to +3VALW for +3VGS Power Leakage issue
	2011/11/25	No.32	V	V	V	Page18, Install Q1400, R1427, R1428 & Remove R1433, R1435 for +3VGS Power Leakage issue
	2011/11/25	No.33	V	V	V	Page33, Modify H10 & H22 From NPTH to PTH For ME Drawing Lose
	2011/11/25	No.34	V	V	V	Page31, Del R2226 for VSB_ON resistor double reserve
	2011/11/26	No.35	V	V	V	Page31, Add R2226, R2227 Pull up to +3VS & Reserve R2217, R2218 pull up to +3VALW for SMBUS Leakage issue
	2011/11/28	No.36	V	V	V	Page7, Del R65, R69 & Reserve R45 & R45 with APU_SID & APU_SIC By Pass APU_SID_R & APU_SIC_R for SMBUS Power Leakage Issue
	2011/11/28	No.37	V	V	V	Page31, Reserve C2219, C2210 to +3VALW For SMBUS2 AC Decoupling
	2011/11/28	No.38	V	V	V	Page31, Del C2213, C2214 & Modify R2226, R2227 BOM Structure to @ & R2217, R2218 to POP For SMBUS Power Leakage issue
	2011/11/29	No.39	V			Page7, Modify R45, R48 BOM Structure to POP & Q9 to @ For SMBUS Power Leakage issue
	2011/11/29	No.40	V			Page36, Modify R2309 P/N from SD028750180(7.5K) to SD028150380(150K) for Power Sequence tuning
	2011/11/29	No.41	V			Page36, Modify C2316 P/N from SE042104K80(0.1U) to SE080105K80(1U) for Power Sequence tuning
	2011/11/29	No.42	V			Page19, Modify R1450 P/N from SD028150380(150K) to SD028130380(130K) for Power Sequence tuning
	2011/11/29	No.43	V			Page19, Modify C1470 P/N from SE042104K80(0.1U) to SE080105K80(1U) for Power Sequence tuning
	2011/11/29	No.44	V			Page13, Modify U4 P/N from SA000041P00(MXIC) to SA00003K800(Winbond) for ROM Part Issue
	2011/11/30	No.45	V			Page19, Modify C1470 P/N from SE080105K80(1U) to SE042104K80(0.1U) for Power Sequence tuning
	2011/11/30	No.46	V			Page19, Modify R1450 P/N from SD028150380(130K) to SD028200280(20K) for Power Sequence tuning
	2011/11/30	No.47	V			Page19, Modify R1449 P/N from SD028200280(20K) to SD02830380(330K) for Power Sequence tuning
	2011/11/30	No.48	V			Page35, unmount R2481 and mount R2482 for LID SW function reserved
	2011/11/30	No.49	V			Page29, unmount R1140 because 14" is no need to select mainstream and retail
	2011/12/02	No.50	V			Page12, Modify C129 P/N from SE071150J80 (15P) to SE071220J80 (22P) For Crystal Clock Tuneing
	2011/12/02	No.51	V			Page12, Modify C130 P/N from SE071150J80 (15P) to SE071270J80 (27P) For Crystal Clock Tuneing
	2011/12/02	No.52	V			Page12, Modify C131, C134 P/N from SE071270J80 (27P) to SE071330J80 (33P) For Crystal Clock Tuneing
	2011/12/02	No.53	V			Page18, Modify C1445, C1446 P/N from SE071120J80 (12P) to SE071200J80 (20P) For Crystal Clock Tuneing
	2011/12/05	No.54	V			Page26, Modify C2144, C2145 BOM Structure to @ for DMIC no function issue
	MEMO	2011/12/09	No.55	V		
2011/12/09		power				power schematics 20110208.dsn

Security Classification				Compal Secret Data		Compal Electronics, Inc.	
Issued Date		2008/08/10		Deciphered Date		2011/03/04	
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Phase	Date	No.	BOM	Sch	Layout	Description
SIT	2012/01/03	No.1	V	V	V	Page31, Add R2228 connect from MAINPWON_R to MAINPWON for Power Circuit update
	2012/01/03	No.2	V	V	V	Page31, Modify R2236 BOM Structure from POP to @ for +3VS Power Leakage Issue
	2012/01/04	No.3	V	V	V	Page7, delete Q9, short and remove 0 ohm: R45&R48
	2012/01/04	No.4	V	V	V	Page7,9,13, short and remove R64&R68, change Page13 net name ML_VGA_HPD, change page7 net name LVDS_HPD
	2012/01/04	No.5	V	V	V	Page15, Modify +VDDA11_USB_S power source from +1.1VALW to +1.1V_FCH for reduce power consumption
	2012/01/04	No.6	V	V	V	Page15, Modify +VDDCR_11V_USB power source from +1.1VALW to +1.1V_FCH for reduce power consumption
	2012/01/04	No.7	V	V	V	Page15, Modify +VDDAN_11_SSUSB & +VDDCR_11_SSUSB power source from +1.1VALW to +1.1V_FCH for reduce power consumption
	2012/01/04	No.8	V	V	V	Page15, Modify +VDDIO_33_S power source from +3V_FCH to +3VALW for reduce power consumption
	2012/01/04	No.9	V	V	V	Page15, Modify +VDDXL_3.3V power source from +3V_FCH to +3VALW for reduce power consumption
	2012/01/04	No.10	V	V	V	Page15, Modify +VDDPL_11_SYS_S power source from +1.1VALW to +1.1V_FCH for reduce power consumption
	2012/01/04	No.11	V	V	V	Page15, Modify +VDDAN_11_SSUSB power source from +3V_FCH to +3VALW for reduce power consumption
	2012/01/04	No.12	V	V	V	Page314, Modify R2318,R2320,R2311 BOM Structure from POP to @ for Reduce Power Consumption
	2012/01/04	No.13	V	V	V	Page36, Add Q2313,Q2314,U2304,C2309,C2312,C2321,R2323,R2310,R2324 for +3VALW to +3V_FCH Circuit (Reduce Power Consumption)
	2012/01/04	No.14	V	V	V	Page36, Add Q2316,Q2309,U2303,C2317,C2320,C2318,C2319,R2322,R2317 for +1.1VALW to +1.1V_FCH Circuit (Reduce Power Consumption)
	2012/01/04	No.15	V	V	V	Page14, Remove R6 & R148 for component part reduce
	2012/01/04	No.16	V	V	V	Page7, Remove R207 for component part reduce
	2012/01/04	No.17	V	V	V	Page322, Remove R471 & R472 for component part reduce
	2012/01/04	No.18	V	V	V	Page29, Remove R1106,R1107,R1119,R1134,R1109 for component part reduce
	2012/01/04	No.19	V	V	V	Page35, Remove R2465,R2466 for component part reduce
	2012/01/04	No.20	V	V	V	Page33, Reserve R2483 & R2485 to connect EC_SMB_CK2 & EC_SMB_DA3 for Lenovo Multi-touch function
	2012/01/04	No.21	V	V	V	Page14, Add R2209 to connect +3VLP to +3VALW_FCH for S4 LID Function (common QILEX)
	2012/01/04	No.22	V	V	V	Page26, Del R2176 to connect to EC_INVPMW for common QILEX
	2012/01/05	No.23	V	V	V	Page14, Add R146 & R148 for component part reduce
	2012/01/05	No.24	V	V	V	Page15, Modify +V_FCH netname to +1VS_FCH for component part reduce
	2012/01/05	No.25	V	V	V	Page36, Modify +1.1V_FCH netname to +1VS_FCH for component part reduce
	2012/01/05	No.26	V	V	V	Page15, Modify +VDDAN_11_USB_S power source from +1.1V_FCH to +1.1VS_FCH for reduce power consumption
	2012/01/05	No.27	V	V	V	Page15, Modify +VDDCR_11V_USB power source from +1.1V_FCH to +1.1VS_FCH for reduce power consumption
	2012/01/05	No.28	V	V	V	Page15, Modify +VDDAN_11_SSUSB & +VDDCR_11_SSUSB power source from +1.1V_FCH to +1.1VS_FCH for reduce power consumption
	2012/01/05	No.29	V	V	V	Page15, Modify +VDDIO_33_S power source from +3VALW to +3VS_FCH for reduce power consumption
	2012/01/05	No.30	V	V	V	Page15, Modify +VDDXL_3.3V power source from +3VALW to +3VS_FCH for reduce power consumption
	2012/01/05	No.31	V	V	V	Page15, Modify +VDDPL_11_SYS_S power source from +1.1V_FCH to +1.1VS_FCH for reduce power consumption
	2012/01/05	No.32	V	V	V	Page15, Modify +VDDAN_33_HWM power source from +3VALW to +3VS_FCH for reduce power consumption
	2012/01/05	No.33	V	V	V	Page29, Remove R1108,R1135,R1110,C1127 for component part reduce
	2012/01/05	No.34	V	V	V	Page31, Remove Pin25 EC_INVPT_PWM for Circuit Common
	2012/01/05	No.35	V	V	V	Page31, Modify EC_U2200 I1Pin from +3VALW_EC to +3VLP for S4 LID Function (common QILEX)
	2012/01/05	No.36	V	V	V	Page15, Modify +3V_FCH netname to +1V_FCH for component part reduce
	2012/01/05	No.37	V	V	V	Page15, Modify +VDDAN_33_USB power source from +3VS_FCH to +3V_FCH for reduce power consumption
	2012/01/05	No.38	V	V	V	Page15, Modify +VDDPL_33_SSUSB_S power source from +3VS_FCH to +3V_FCH for reduce power consumption
	2012/01/05	No.39	V	V	V	Page15, Modify +VDDPL_33_USB_S power source from +3VS_FCH to +3V_FCH for reduce power consumption
	2012/01/05	No.40	V	V	V	Page15, Modify +VDDIO_33_S power source from +3V_FCH to +3VALW for reduce power consumption
	2012/01/05	No.41	V	V	V	Page15, Modify +VDDAN_33_HWM power source from +3V_FCH to +3VALW for reduce power consumption
	2012/01/05	No.42	V	V	V	Page36, Add U2302 From +1.1VALW to +1.1V_FCH for reduce power consumption
	2012/01/05	No.43	V	V	V	Page36, Modify U2304 Power source from +3V_FCH to +3V for reduce power consumption
	2012/01/05	No.44	V	V	V	Page36, Add U2303 from +3VALW to +3V for reduce power consumption
	2012/01/05	No.45	V	V	V	Page36, Modify U2303 Power source from +1.1V_FCH to +1.1V for reduce power consumption
	2012/01/05	No.46	V	V	V	Page36, Modify U2302 From +1.1V_FCH to +1.1V for reduce power consumption
	2012/01/05	No.47	V	V	V	Page15, Modify +VDDAN_11_USB_S power source from +1.1V_FCH to +1.1V for reduce power consumption
	2012/01/05	No.48	V	V	V	Page15, Modify +VDDCR_11V_USB power source from +1.1V_FCH to +1.1V for reduce power consumption
	2012/01/05	No.49	V	V	V	Page15, Modify +VDDAN_11_SSUSB & +VDDCR_11_SSUSB power source from +1.1V_FCH to +1.1V for reduce power consumption
	2012/01/05	No.50	V	V	V	Page15, Modify +VDDPL_11_SYS_S power source from +1.1V_FCH to +1.1V for reduce power consumption
	2012/01/05	No.51	V	V	V	Page15, Modify +VDDAN_33_USB power source from +3V_FCH to +3V for reduce power consumption
	2012/01/05	No.52	V	V	V	Page15, Modify +VDDPL_33_SSUSB_S power source from +3V_FCH to +3V for reduce power consumption
	2012/01/05	No.53	V	V	V	Page15, Modify +VDDPL_33_USB_S power source from +3V_FCH to +3V for reduce power consumption
	2012/01/05	No.54	V	V	V	Page15, Modify +VDDIO_33_S power source from +3VALW to +3V_FCH for reduce power consumption
	2012/01/05	No.55	V	V	V	Page15, Modify +VDDAN_33_HWM power source from +3VALW to +3V_FCH for reduce power consumption
	2012/01/06	No.56	V	V	V	Page15, Modify +VDDXL_3.3V power source from +3V_FCH to +3V for reduce power consumption
	2012/01/09	No.57	V	V	V	Page33, Add R2493,R2492,R2491,R2494,Q2403,Q2400,C2494,C2493 for AOAC Power Circuit
	2012/01/09	No.58	V	V	V	Page31, U2200 add netname FCH_PWR_EN# on Pin70 for +3V & +1.1V Power Control
	2012/01/09	No.59	V	V	V	Page36, Add R2325 from FCH_PWR_EN# to FCH_PWR_EN#_R for +3V & +1.1V Power Control
	2012/01/09	No.60	V	V	V	Page36, Add FCH_PWR_EN#_R on Q2313.2,Q2314.2,Q2316.2,Q2309.2 for +3V & +1.1V Power Control Enable Option
	2012/01/09	No.61	V	V	V	Page33, Modify JMIN11 pin1 from FCH_PCIE_WAKE# to WLAN_WAKE# for AOAC Function
	2012/01/09	No.62	V	V	V	Page31, Modify U2200 Pin26 from EAPD_R to WLAN_WAKE# for AOAC Function
	2012/01/09	No.63	V	V	V	Page31, Add U2200 Pin19 from NC to EAPD_R for Audio Function
	2012/01/09	No.64	V	V	V	Page31, Add U2200 Pin91 from NC to AOAC_WLAN for AOAC Function
	2012/01/10	No.65	V	V	V	Page31, Modify U2200 Pin19 net name from ODD_DA# to WL_OFF_EC# for Circuit common with Intel
	2012/01/10	No.66	V	V	V	Page30, Del R2435 for component reduce
	2012/01/10	No.67	V	V	V	Page33, Add R2496 & reserve R2495 for RF_OFF# source option
	2012/01/10	No.68	V	V	V	Page33, Modify JMIN11 Pin20 net name from WL_OFF# to RF_OFF# for Circuit common with Intel
	2012/01/10	No.69	V	V	V	Page31, Modify R2205 BOM Structure to @ for Common Circuit with Intel
	2012/01/10	No.70	V	V	V	Page31, Modify R2232,R2230 from 10K to 100K & Modify R2202,R2230,R2232 pull up from +3VALW_EC to +3VALW for Common Circuit with Intel
	2012/01/11	No.71	V	V	V	Page31, Modify L2200.1 Power Source from +3VALW to +3VALW_EC for EC_AVCC Power Leakage Issue
	2012/01/11	No.72	V	V	V	Page31, BRDID Table update for SIT Build
	2012/01/11	No.73	V	V	V	Page31, Modify R2209 From 18K to 33K for FVT BRDID update
	2012/01/11	No.74	V	V	V	Page26, Modify R2166 P/N from SD028330080 (33ohm) to SD034499180 (4.99K) for logo led brightness fine tune
	2012/01/11	No.75	V	V	V	Page35, Remove R2469 for logo led brightness fine tune
MEMO	2012/01/11	No.76	V			Page18, Modify C1445,C1446 P/N from SE071200JN0 to SE071200J80 for FVT SMT Memo
	2012/01/11	No.77	V			Page36, Modify C2316 P/N from SE080105K80 to SE0000069L0 for FVT SMT Memo
	2012/01/11	No.78	V			Page26, Add C2144,C2145 P/N SE071220J80 (22p)for FVT SMT Memo
	2012/01/11	No.79	V	V	V	Page36, Add Q2317 to Replace U2303 for +1.1V Power Mos layout space not enough issue
	2012/01/11	No.80	V	V	V	Page36, Add Q2318 to Replace U2304 for +3V Power Mos layout space not enough issue
	2012/01/11	No.81	V	V	V	Page29, Modify R1102,R1104,R1105 BOM Structure to @ for Vendor suggestion
	2012/01/12	No.82	V	V	V	Page36, Modify R2323.1 & R2322.1 from +VSB to +5VALW for VGS over spec issue
	2012/01/12	No.83	V	V	V	Page317, Modify Q2317 & Q2318 P/N: from SB00000LQ00 to SB923050030 for VGS over spec issue
	2012/01/12	No.84	V	V	V	Page31.35 Modify U2200 Pin70 Net name from FCH_PWR_EN# to FCH_PWR_EN for +3V & +1.1V power control solution change
	2012/01/12	No.85	V	V	V	Page36, Modify R2325 to POP from FCH_PWR_EN to FCH_PWR_EN_R for +3V & +1.1V Power Control
	2012/01/12	No.86	V	V	V	Page36, Delete R2314,R2318,R2320,Q2311 for Reduce Power Consumption
	2012/01/16	No.87	V			Page31, Modify R2230 BOM Structure from POP to @ for double pull up error
	2012/01/16	No.88	V			Page31, Modify R2208 BOM Structure from POP to @ for internal pull high solution

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Issued Date	2008/08/10	Deciphered Date	2011/03/04	Title	EE modify list
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